SSD1307

Advance Information

128 x 39 Dot Matrix **OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.



Appendix: IC Revision history of SSD1307 Specification

Version	Change Items	Effective Date
1.0	 Changed to Advance Information Update the TBD values in Table 11-1 : DC Characteristics Update the TBD values in Table 12-1 : AC Characteristics 	28-Dec-07
1.1	 Revised section 7.9 Power ON and OFF sequence (power OFF sequence 3 and note 4) Typo: Revise command table 26/27h: E[6:0] to E[7:0], F[6:0] to F[7:0] Add SSD1307Z die tray information 	22-Feb-08
1.2	 Revised the frame freq formula (K) – P.20 Revise typo on CL pin connection P.20 Remove t_{AS} & t_{AH} timing in Table 12.5 Revise typo in Figure 12.4 Add D0 pin in Table 7.4 & Table 7.5 	16-Oct-08

 Solomon Systech
 Oct 2008
 P 2/55
 Rev 1.2
 SSD1307

CONTENT

1	GENERAL DESCRIPTION	
2	FEATURES	7
3	ORDERING INFORMATION	
4	BLOCK DIAGRAM	
5	DIE PAD FLOOR PLAN	
	PIN DESCRIPTION	
6		
7	FUNCTIONAL BLOCK DESCRIPTIONS	
7.1 7.2 7.3 7.4 7.5 7.6 7.7 7.8 7.9	MCU Interface selection 7.1.1 MCU Parallel 6800-series Interface 7.1.2 MCU Parallel 8080-series Interface 7.1.3 MCU Serial Interface (4-wire SPI) 7.1.4 MCU Serial Interface (3-wire SPI) 7.1.5 MCU I ² C Interface Command Decoder Oscillator Circuit and Display Time Generator FR synchronization Reset Circuit Segment Drivers / Common Drivers Graphic Display Data RAM (GDDRAM) SEG/COM Driving block Power ON and OFF sequence	13 14 15 16 17 20 20 21 21 22 23
8	COMMAND TABLE	26
8.1	Data Read / Write	33
9	COMMAND DESCRIPTIONS	34
9.1	FUNDAMENTAL COMMAND 9.1.1 Set Lower Column Start Address for Page Addressing Mode (00h~0Fh) 9.1.2 Set Higher Column Start Address for Page Addressing Mode (10h~17h). 9.1.3 Set Memory Addressing Mode (20h). 9.1.4 Set Column Address (21h). 9.1.5 Set Page Address (22h). 9.1.6 Set Display Start Line (40h~66h). 9.1.7 Set Contrast Control for BANKO (81h). 9.1.8 Set Segment Re-map (A0h/A1h). 9.1.9 Entire Display ON (A4h/A5h). 9.1.10 Set Normal/Inverse Display (A6h/A7h). 9.1.11 Set Multiplex Ratio (A8h). 9.1.12 Set Display ON/OFF (AEh/AFh). 9.1.13 Set Page Start Address for Page Addressing Mode (B0h~B4h). 9.1.14 Set COM Output Scan Direction (C0h/C8h). 9.1.15 Set Display Offset (D3h). 9.1.16 Set Display Clock Divide Ratio/ Oscillator Frequency (D5h). 9.1.17 Set Pre-charge Period (D9h). 9.1.18 Set COM Pins Hardware Configuration (DAh) 9.1.19 Set V _{COMH} Deselect Level (DBh).	34 34 34 35 36 36 37 37 37 37 37 41 41
9.2	9.1.20 NOP (E3h) 9.1.21 Status register Read. GRAPHIC ACCELERATION COMMAND 9.2.1 Horizontal Scroll Setup (26h/27h) 9.2.2 Continuous Vertical and Horizontal Scroll Setup (29h/2Ah).	41 42

	9.2.4 Activate Scroll (2Fh)	43
	9.2.4 Activate Scroll (2Fh)	43
10	MAXIMUM RATINGS	45
11	DC CHARACTERISTICS	46
12	AC CHARACTERISTICS	47
13	APPLICATION EXAMPLE	53
14	PACKAGE INFORMATION	54
14.	.1 SSD1307Z DIE TRAY INFORMATION	54

 Solomon Systech
 Oct 2008
 P 4/55
 Rev 1.2
 SSD1307

FIGURES

Figure 4-1: SSD1307 Block Diagram	8
Figure 5-1: SSD1307Z Die Drawing	9
Figure 7-1: Data read back procedure - insertion of dummy read	14
Figure 7-2 : Example of Write procedure in 8080 parallel interface mode	14
Figure 7-3: Example of Read procedure in 8080 parallel interface mode	14
Figure 7-4: Display data read back procedure - insertion of dummy read	15
Figure 7-5: Write procedure in 4-wire Serial interface mode	16
Figure 7-6: Write procedure in 3-wire Serial interface mode	
Figure 7-7: I ² C-bus data format	18
Figure 7-8: Definition of the Start and Stop Condition	19
Figure 7-9: Definition of the acknowledgement condition	19
Figure 7-10: Definition of the data transfer condition	19
Figure 7-11 : Oscillator Circuit and Display Time Generator	20
Figure 7-12 : Segment Output Waveform in three phases	22
Figure 7-13 : GDDRAM pages structure of SSD1307	23
Figure 7-14 : I _{REF} Current Setting by Resistor Value	24
Figure 7-15: The Power ON sequence	25
Figure 7-16: The Power OFF sequence	
Figure 9-1 : Address Pointer Movement of Page addressing mode	
Figure 9-2: Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-remapping)	
Figure 9-3 : Address Pointer Movement of Horizontal addressing mode	
Figure 9-4 : Address Pointer Movement of Vertical addressing mode	
Figure 9-5 : Example of Column and Row Address Pointer Movement	
Figure 9-6 : Transition between different modes	
Figure 9-7: Example of row address mapping	
Figure 9-8: Horizontal scroll example: Scroll RIGHT by 1 column	
Figure 9-9: Horizontal scroll example: Scroll LEFT by 1 column	
Figure 9-10 : Horizontal scrolling setup example	
Figure 9-11 : Continuous Vertical and Horizontal scrolling setup example	
Figure 9-12 : Vertical scroll area setup examples	
Figure 12-1: 6800-series MCU parallel interface characteristics.	
Figure 12-2: 8080-series parallel interface characteristics.	
Figure 12-3 : Serial interface characteristics (4-wire SPI)	
Figure 12-4: Serial interface characteristics (3-wire SPI)	
Figure 12-5: I ² C interface Timing characteristics	
Figure 13-1: Application Example of SSD1307Z.	
Figure 14-1 SSD1307Z die tray information	54

SSD1307 Rev 1.2 P 5/55 Oct 2008 **Solomon Systech**

TABLE

7
10
11
12
13
13
15
15
16
26
30
33
33
39
40
45
46
47
48
49
50
51
52

 Solomon Systech
 Oct 2008
 P 6/55
 Rev 1.2
 SSD1307

1 GENERAL DESCRIPTION

SSD1307 is a single-chip CMOS OLED/PLED driver with controller for organic / polymer light emitting diode dot-matrix graphic display system. It consists of 128 segments and 39 commons. This IC is designed for Common Cathode type OLED panel.

The SSD1307 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. It has 256-step brightness control. Data/Commands are sent from general MCU through the hardware selectable 6800/8080 series compatible Parallel Interface, I²C interface or Serial Peripheral Interface. It is suitable for many compact portable applications, such as mobile phone sub-display, MP3 player and calculator, etc.

2 FEATURES

- Resolution: 128 x 39 dot matrix panel
- Power supply
 - o $V_{DD} = 1.65 V \sim 3.3 V$ (IC logic)
 - o $V_{CC} = 7V \sim 15V$ (Panel driving power supply)
- For matrix display
 - o OLED driving output voltage, 15V maximum
 - o Segment maximum source current: 320uA
 - o Common maximum sink current: 40mA
 - o 256 step contrast brightness current control
- Embedded 128 x 39 bit SRAM display buffer
- Pin selectable MCU Interfaces:
 - o 8-bit 6800/8080-series parallel interface
 - o 3 /4 wire Serial Peripheral Interface
 - I²C Interface
- Screen saving continuous scrolling function in both horizontal and vertical direction
- Programmable Frame Rate
- Programmable Multiplexing Ratio
- Row Re-mapping and Column Re-mapping
- On-Chip Oscillator
- Chip layout for COG, COF
- Wide range of operating temperature: -40°C to 85°C

3 ORDERING INFORMATION

Table 3-1: Ordering Information

Ordering Part Number	SEG	СОМ	Package Form	Reference	Remark	
SSD1307Z	128	39	COG	Page 9	 Min SEG pad pitch: 32.4um Min COM pad pitch: 40um Die thickness: 300 +/- 25 um 	

SSD1307 | Rev 1.2 | P 7/55 | Oct 2008 | **Solomon Systech**

4 BLOCK DIAGRAM

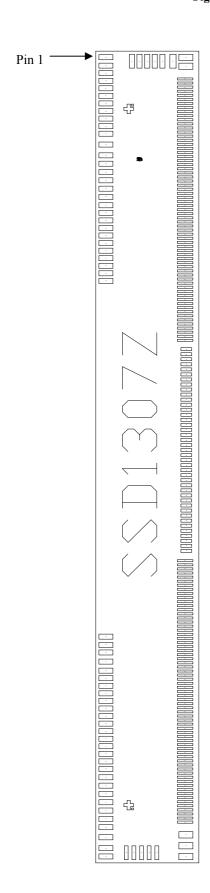
RES# **SEG 63** CS# D/C# E (RD#) R/W#(WR#) **SEG 62** Segment Driver SEG1 Graphic Display Data RAM (GDDRAM) BS2 BS1 BS0 SEG0 Display Controller MCU Interface COM 0 Common Driver COM 1 COM37 COM38 $\begin{matrix} V_{DD} \\ V_{CC} \\ V_{SS} \\ V_{LSS} \end{matrix}$ ¥ Voltage Control Current Control Command Decoder **SEG 64** Segment Driver Oscillator **SEG 65 SEG126 SEG127** CLS

Figure 4-1: SSD1307 Block Diagram

 Solomon Systech
 Oct 2008
 P 8/55
 Rev 1.2
 SSD1307

5 **DIE PAD FLOOR PLAN**

Figure 5-1: SSD1307Z Die Drawing

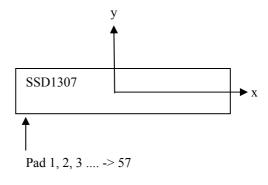


Die Size	6.44mm x 0.81mm
Die Thickness	$300 \text{ um} \pm 25 \text{ um}$
Min I/O pad pitch	60 um
Min SEG pad pitch	32.4 um
Min COM pad pitch	40 um
Bump Height	Nominal 15 um

Bump Size		
Pad #	X [um]	Y [um]
1~57	40	110
240~244	110	40
58~62	110	30
63~65, 237~238	50	110
66~130 , 172~236	16.4	122
131~171	24	84
239	110	50

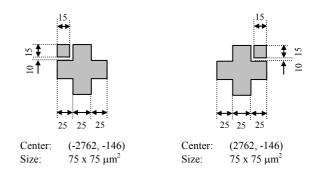
- Note

 (1) Diagram showing the Gold bumps face up.
 (2) Coordinates are referenced to center of the chip.
- (3) Coordinate units and size of all alignment marks are
- (4) All alignment keys do not contain gold



Gold Bumps face up

Figure 5-2: SSD1307Z Alignment mark dimensions



P 9/55 SSD1307 Rev 1.2 Oct 2008 Solomon Systech

Table 5-1: SSD1307Z Bump Die Pad Coordinates

Pin number	Pin name	X	Υ	Pin number		Х	Υ	Pin number	Pin name	X	Υ
1	NC	-3171.0	-325.0	81	SEG48	2410.6	297.3	161	COM29	-455.2	306.0
2	VCC	-3105.0	-325.0	82	SEG47	2378.2	297.3	162	COM30	-495.2	306.0
3	VCC	-3045.0	-325.0	83	SEG46	2345.8	297.3	163	COM31	-535.2	306.0
4	VCC	-2985.0	-325.0	84	SEG45	2313.4	297.3	164	COM32	-575.2	306.0
5	VCC	-2925.0	-325.0	85	SEG44	2281.0	297.3	165	COM33	-615.2	306.0
6	NC	-2865.0	-325.0	86	SEG43	2248.6	297.3	166	COM34	-655.2	306.0
7	VLSS	-2805.0	-325.0	87	SEG43	2216.2	297.3	167	COM35	-695.2	306.0
8	VLSS	-2745.0	-325.0	88	SEG41	2183.8	297.3	168	COM36	-735.2	306.0
9	VSS	-2685.0	-325.0	89	SEG40	2151.4	297.3	169	COM37	-775.2	306.0
10	NC	-2625.0	-325.0	90	SEG39	2119.0	297.3	170	COM38	-815.2	306.0
11	VDD	-2565.0	-325.0	91	SEG38	2086.6	297.3	171	NC	-855.2	306.0
12	VDD	-2479.0	-325.0	92	SEG37	2054.2	297.3	172	VCOMH	-925.7	297.3
13	FR	-2393.0	-325.0	93	SEG36	2021.8	297.3	173	SEG64	-958.1	297.3
14	VSS	-2327.0	-325.0	94	SEG35	1989.4	297.3	174	SEG65	-990.5	297.3
15	CS#	-2261.0	-325.0	95	SEG34	1957.0	297.3	175	SEG66	-1022.9	297.3
16	RES#	-2195.0	-325.0	96	SEG33	1924.6	297.3	176	SEG67	-1055.3	297.3
17	D/C#	-2129.0	-325.0	97	SEG32	1892.2	297.3	177	SEG68	-1087.7	297.3
18											
	VSS	-2063.0	-325.0	98	SEG31	1859.8	297.3	178	SEG69	-1120.1	297.3
19	R/W#(WR#)	-1997.0	-325.0	99	SEG30	1827.4	297.3	179	SEG70	-1152.5	297.3
20	E(RD#)	-1937.0	-325.0	100	SEG29	1795.0	297.3	180	SEG71	-1184.9	297.3
21	D0	-1877.0	-325.0	101	SEG28	1762.6	297.3	181	SEG72	-1217.3	297.3
22	D1	-1817.0	-325.0	102	SEG27	1730.2	297.3	182	SEG73	-1249.7	297.3
23	D2	-1757.0	-325.0	103	SEG26	1697.8	297.3	183	SEG74	-1282.1	297.3
24	D3	-1697.0	-325.0	104	SEG25	1665.4	297.3	184	SEG75	-1314.5	297.3
25	VSS	-1637.0	-325.0	105	SEG24	1633.0	297.3	185	SEG76	-1346.9	297.3
26	D4	-1577.0	-325.0	106	SEG23	1600.6	297.3	186	SEG77	-1379.3	297.3
27	D5	-1517.0	-325.0	107	SEG22	1568.2	297.3	187	SEG78	-1411.7	297.3
28	D6	-1457.0	-325.0	108	SEG21	1535.8	297.3	188	SEG79	-1444.1	297.3
29	D7	-1397.0	-325.0	109	SEG20	1503.4	297.3	189	SEG80	-1476.5	297.3
									SEG80 SEG81		
30	IREF	1425.0	-325.0	110	SEG19	1471.0	297.3	190		-1508.9	297.3
31	VLSS	1491.0	-325.0	111	SEG18	1438.6	297.3	191	SEG82	-1541.3	297.3
32	VLSS	1551.0	-325.0	112	SEG17	1406.2	297.3	192	SEG83	-1573.7	297.3
33	NC	1623.0	-325.0	113	SEG16	1373.8	297.3	193	SEG84	-1606.1	297.3
34	VCOMH	1695.0	-325.0	114	SEG15	1341.4	297.3	194	SEG85	-1638.5	297.3
35	VCOMH	1755.0	-325.0	115	SEG14	1309.0	297.3	195	SEG86	-1670.9	297.3
36	VCOMH	1815.0	-325.0	116	SEG13	1276.6	297.3	196	SEG87	-1703.3	297.3
37	VCOMH	1875.0	-325.0	117	SEG12	1244.2	297.3	197	SEG88	-1735.7	297.3
38	VCC	1935.0	-325.0	118	SEG11	1211.8	297.3	198	SEG89	-1768.1	297.3
39	VCC	1995.0	-325.0	119	SEG10	1179.4	297.3	199	SEG90	-1800.5	297.3
40	VCC	2055.0	-325.0	120	SEG9	1147.0	297.3	200	SEG91	-1832.9	297.3
41	VCC	2115.0	-325.0	121	SEG8	1114.6	297.3	201	SEG92	-1865.3	297.3
42	CL	2175.0	-325.0	122	SEG7	1082.2	297.3	202	SEG93	-1897.7	297.3
43	VSS	2235.0	-325.0	123	SEG6	1049.8	297.3	203	SEG94	-1930.1	297.3
44	VSS	2295.0	-325.0	124	SEG5	1017.4	297.3	204	SEG95	-1962.5	297.3
45	CLS	2355.0	-325.0	125	SEG4	985.0	297.3	205	SEG96	-1994.9	297.3
46	VDD	2415.0	-325.0	126	SEG3	952.6	297.3	206	SEG97	-2027.3	297.3
47	BS0	2475.0	-325.0	127	SEG2	920.2	297.3	207	SEG98	-2059.7	297.3
48	VSS	2541.0	-325.0	128	SEG1	887.8	297.3	208	SEG99	-2092.1	297.3
49	BS1	2607.0	-325.0	129	SEG0	855.4	297.3	209	SEG100	-2124.5	297.3
50	VDD	2673.0	-325.0	130	VCOMH	823.0	297.3	210	SEG101	-2156.9	297.3
51	VDD	2739.0	-325.0	131	NC	744.8	306.0	211	SEG102	-2189.3	297.3
52	BS2	2805.0	-325.0	132	COM0	704.8	306.0	212	SEG103	-2221.7	297.3
53	VSS	2871.0	-325.0	133	COM1	664.8	306.0	213	SEG103	-2254.1	297.3
	TRB0	2937.0			COM1			214	SEG104 SEG105	-2286.5	297.3
54			-325.0	134		624.8	306.0				
55	VDD TDD4	3017.0	-325.0	135	COM3	584.8	306.0	215	SEG106	-2318.9	297.3
56	TRB1	3103.0	-325.0	136	COM4	544.8	306.0	216	SEG107	-2351.3	297.3
57	VSS	3169.0	-325.0	137	COM5	504.8	306.0	217	SEG108	-2383.7	297.3
58	TRA3	3140.0	-165.2	138	COM6	464.8	306.0	218	SEG109	-2416.1	297.3
59	TRA2	3140.0	-105.2	139	COM7	424.8	306.0	219	SEG110	-2448.5	297.3
60	VSS	3140.0	-45.2	140	COM8	384.8	306.0	220	SEG111	-2480.9	297.3
61	TRA1	3140.0	14.8	141	COM9	344.8	306.0	221	SEG112	-2513.3	297.3
62	TRA0	3140.0	74.8	142	COM10	304.8	306.0	222	SEG113	-2545.7	297.3
63	VCC	3170.0	303.3	143	COM11	264.8	306.0	223	SEG114	-2578.1	297.3
64	VLSS	3083.7	303.3	144	COM12	224.8	306.0	224	SEG115	-2610.5	297.3
65	VLSS	2997.4	303.3	145	COM13	184.8	306.0	225	SEG116	-2642.9	297.3
66	SEG63	2896.6	297.3	146	COM13	144.8	306.0	226	SEG117	-2675.3	297.3
67		2864.2	297.3	147	COM14 COM15	104.8	306.0	227	SEG117 SEG118	-2075.3	297.3
	SEG62										
68	SEG61	2831.8	297.3	148	COM16	64.8	306.0	228	SEG119	-2740.1	297.3
69	SEG60	2799.4	297.3	149	COM17	24.8	306.0	229	SEG120	-2772.5	297.3
70	SEG59	2767.0	297.3	150	COM18	-15.2	306.0	230	SEG121	-2804.9	297.3
71	SEG58	2734.6	297.3	151	COM19	-55.2	306.0	231	SEG122	-2837.3	297.3
72	SEG57	2702.2	297.3	152	COM20	-95.2	306.0	232	SEG123	-2869.7	297.3
73	SEG56	2669.8	297.3	153	COM21	-135.2	306.0	233	SEG124	-2902.1	297.3
74	SEG55	2637.4	297.3	154	COM22	-175.2	306.0	234	SEG125	-2934.5	297.3
75	SEG54	2605.0	297.3	155	COM23	-215.2	306.0	235	SEG126	-2966.9	297.3
76	SEG53	2572.6	297.3	156	COM24	-255.2	306.0	236	SEG127	-2999.3	297.3
77	SEG52	2540.2	297.3	157	COM25	-295.2	306.0	237	VCC	-3100.0	303.3
78	SEG52 SEG51	2507.8	297.3	158	COM26	-335.2	306.0	238	VCC	-3170.0	303.3
79	SEG50	2475.4	297.3	159	COM27	-375.2	306.0	239	NC	-3140.0	201.8
80	SEG50 SEG49	2443.0	297.3	160	COM28	-375.2 -415.2	306.0	240	VCC	-3140.0	119.0
- 60	JEG49	∠++3.0	231.3	100	COIVIZO	-+1J.Z	500.0	240	VUC	-0140.0	118.0

Pin number	Pin name	X	Υ
241	VCC	-3140.0	59.0
242	VCOMH	-3140.0	-1.0
243	VCOMH	-3140.0	-61.0
244	VLSS	-3140.0	-121.0

 Solomon Systech
 Oct 2008
 P 10/55
 Rev 1.2
 SSD1307

6 PIN DESCRIPTION

Key:

I = Input	NC = Not Connected
O =Output	Pull LOW= connect to Ground
I/O = Bi-directional (input/output)	Pull HIGH= connect to V _{DD}
P = Power pin	

Table 6-1: Pin Description

Pin Name	Type	Description
V_{DD}	P	Power supply pin for core logic operation.
V_{CC}	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
V_{SS}	P	This is a ground pin.
V _{LSS}	P	This is an analog ground pin. It should be connected to V_{SS} externally.
V_{COMH}	О	The pin is for COM signal deselected voltage level. A capacitor should be connected between this pin and $V_{\rm SS}$.
BS[2:0]	I	MCU bus interface selection pins. Please refer to Table 6-2 for the details of setting.
I _{REF}	I	This is segment output current reference pin. A resistor should be connected between this pin and V_{SS} to maintain the I_{REF} current at 10 uA. Please refer to Figure 7-14 for the details of resistor value.
FR	O	This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used. Please refer to Section 7.4 for details usage.
CL	I	This is external clock input pin. When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and should be connected to $V_{\rm SS}$. When internal clock is disabled (i.e. LOW in CLS pin), this pin is the external clock source input pin.
CLS	I	This is internal clock enable pin. When it is pulled HIGH (i.e. connect to VDD), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.
RES#	I	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to $V_{\rm DD}$) during normal operation.
CS#	I	This pin is the chip select input. (active LOW)
D/C#	I	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to V_{DD}), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I ² C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to V_{SS} . For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams: Figure 12-1 to Figure 12-5.

SSD1307 Rev 1.2 P 11/55 Oct 2008 **Solomon Systech**

Pin Name	Type	Description
E (RD#)	I	When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to V_{DD}) and the chip is selected. When connecting to an 8080-series microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial interface is selected, this pin must be connected to V_{SS} .
R/W#(WR#)	I	This is read / write control input pin connecting to the MCU interface. When interfacing to a 6800-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH (i.e. connect to VDD) and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to $V_{\rm SS}$.
D[7:0]	IO	These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I^2C mode is selected, D2, D1 should be tied together and serve as SDA_{out} , SDA_{in} in application and D0 is the serial clock input, SCL.
TRA[3:0]	-	Reserved pin and is recommended to keep it float.
TRB[1:0]	-	Reserved pin and is recommended to be connected to V_{SS} .
SEG0 ~ SEG127	О	These pins provide Segment switch signals to OLED panel. These pins are V_{SS} state when display is OFF.
COM0 ~ COM39	0	These pins provide Common switch signals to OLED panel. They are in high impedance state when display is OFF.
NC	-	This is dummy pin. Do not group or short NC pins together.

Table 6-2: MCU Bus Interface Pin Selection

SSD1307 Pin Name	I ² C Interface	-	8080-parallel interface (8 bit)	4-wire Serial interface	3-wire Serial interface
BS0	0	0	0	0	1
BS1	1	0	1	0	0
BS2	0	1	1	0	0

Oct 2008 P 12/55 Rev 1.2 SSD1307 **Solomon Systech**

 $[\]begin{array}{l} \textbf{Note} \\ ^{(1)} \ 0 \ \text{is connected to} \ V_{SS} \\ ^{(2)} \ 1 \ \text{is connected to} \ V_{DD} \end{array}$

7 FUNCTIONAL BLOCK DESCRIPTIONS

7.1 MCU Interface selection

SSD1307 MCU interface consist of 8 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 7-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 6-2 for BS[2:0] setting).

Table 7-1: MCU interface assignment under different bus interface mode

Pin Name	Data/C	eata/Command Interface Control Signal												
Bus														
Interface	D7	D6	D5	D4	D3	D 0	E	R/W#	CS#	D/C#	RES#			
8-bit 8080				D	[7:0]				RD#	WR#	CS#	D/C#	RES#	
8-bit 6800				D	[7:0]				Е	R/W#	CS#	D/C#	RES#	
3-wire SPI	Tie LO	W				NC	SDIN	SCLK	Tie L	OW	CS#	Tie LOW	RES#	
	Tie LO	W				NC	SDIN	SCLK	Tie LOW CS#		D/C#	RES#		
I^2C	Tie LO	W				SDA _{OUT}	SDA_{IN}	SCL	CL Tie LOW SA0			SA0	RES#	

7.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation. A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

Table 7-2: Control pins of 6800 interface

Function	E	R/W #	CS#	D/C#
Write command	↓	L	L	L
Read status	↓	Н	L	L
Write data	↓	L	L	Н
Read data	↓	Н	L	Н

Note

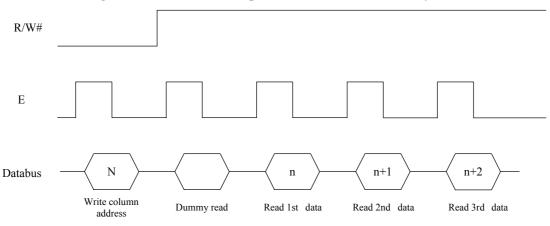
(1) ↓ stands for falling edge of signal H stands for HIGH in signal

L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 7-1.

SSD1307 | Rev 1.2 | P 13/55 | Oct 2008 | **Solomon Systech**

Figure 7-1: Data read back procedure - insertion of dummy read



7.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW. A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 7-2: Example of Write procedure in 8080 parallel interface mode

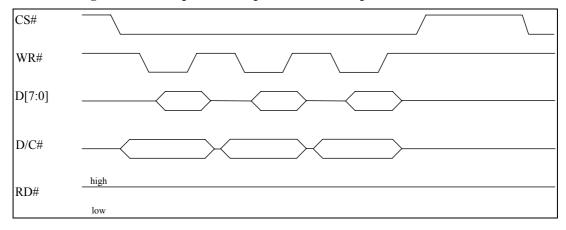
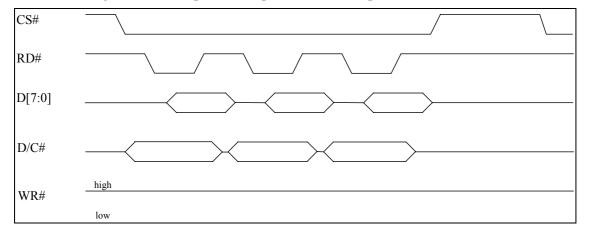


Figure 7-3: Example of Read procedure in 8080 parallel interface mode



Solomon Systech Oct 2008 | P 14/55 | Rev 1.2 | SSD1307

Table 7-3: Control pins of 8080 interface

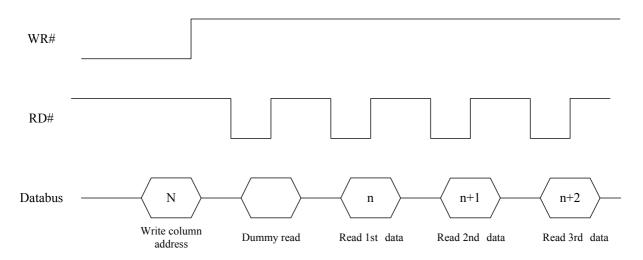
Function	RD#	WR#	CS#	D/C#
Write command	Н	↑	L	L
Read status	↑	Н	L	L
Write data	Н	↑	L	Н
Read data	↑	Н	L	Н

Note

- $^{(1)}$ \uparrow stands for rising edge of signal
- (2) H stands for HIGH in signal
- (3) L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 7-4.

Figure 7-4: Display data read back procedure - insertion of dummy read



7.1.3 MCU Serial Interface (4-wire SPI)

The 4-wire serial interface consists of serial clock: SCLK, serial data: SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W# (WR#)# can be connected to an external ground.

Table 7-4: Control pins of 4-wire Serial interface

Function	E	R/W#	CS#	D/C#	D 0
Write command	Tie LOW	Tie LOW	L	L	↑
Write data	Tie LOW	Tie LOW	L	Н	1

Note

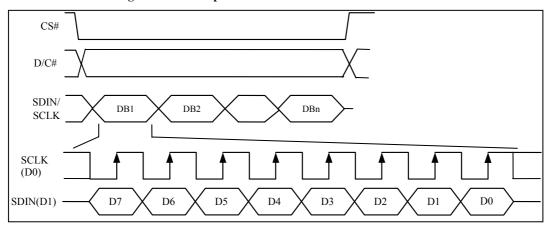
- (1) H stands for HIGH in signal
- (2) L stands for LOW in signal
- (3) ↑ stands for rising edge of signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock.

Under serial mode, only write operations are allowed.

SSD1307 | Rev 1.2 | P 15/55 | Oct 2008 | **Solomon Systech**

Figure 7-5: Write procedure in 4-wire Serial interface mode



MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#. In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, R/W# (WR#)#, E and D/C# can be connected to an external ground.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0). Under serial mode, only write operations are allowed.

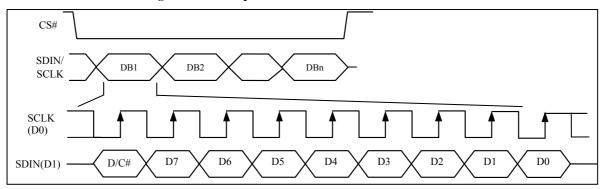
Table 7-5: Control pins of 3-wire Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0	Note
Write command	Tie LOW	Tie LOW	L	Tie LOW	↑	(1) L
Write data	Tie LOW	Tie LOW	L	Tie LOW	1	(2) ↑ S

stands for LOW in signal

stands for rising edge of signal

Figure 7-6: Write procedure in 3-wire Serial interface mode



Solomon Systech Oct 2008 P 16/55 Rev 1.2 SSD1307

7.1.5 MCU I²C Interface

The I^2C communication interface consists of slave address bit SA0, I^2C -bus data signal SDA (SDA_{OUT}/D₂ for output and SDA_{IN}/D₁ for input) and I^2C -bus clock signal SCL (D₀). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)

SSD1307 has to recognize the slave address before transmitting or receiving any information by the I²C-bus. The device will respond to the slave address following by the slave address bit ("SA0" bit) and the read/write select bit ("R/W#" bit) with the following byte format,

"SA0" bit provides an extension bit for the slave address. Either "0111100" or "0111101", can be selected as the slave address of SSD1307. D/C# pin acts as SA0 for slave address selection. "R/W#" bit is used to determine the operation mode of the I²C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

b) I²C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.

It should be noticed that the ITO track resistance and the pulled-up resistance at "SDA" pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in "SDA".

"SDA $_{IN}$ " and "SDA $_{OUT}$ " are tied together and serve as SDA. The "SDA $_{IN}$ " pin must be connected to act as SDA. The "SDA $_{OUT}$ " pin may be disconnected. When "SDA $_{OUT}$ " pin is disconnected, the acknowledgement signal will be ignored in the I^2C -bus.

c) I²C-bus clock signal (SCL)

The transmission of information in the I²C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

SSD1307 | Rev 1.2 | P 17/55 | Oct 2008 | **Solomon Systech**

7.1.5.1 I²C-bus Write data

The I²C-bus interface gives access to write data and command into the device. Please refer to Figure 7-7 for the write mode of I²C-bus in chronological order.

Note: Co - Continuation bit D/C# - Data / Command Selection bit ACK - Acknowledgement SA0 - Slave address bit R/W# - Read / Write Selection bit S – Start Condition / P – Stop Condition Write mode Control byte Control byte Data byte 1 byte Slave Address $n \ge 0$ bytes $m \ge 0$ words MSR LSB 011110 Slave Address Control byte

Figure 7-7: I²C-bus data format

7.1.5.2 Write mode for I2C

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 7-8. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD1307, the slave address is either "b0111100" or "b0111101" by changing the SA0 to LOW or HIGH (D/C pin acts as SA0).
- 3) The write mode is established by setting the R/W# bit to logic "0".
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 7-9 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six "0" 's.
 - a. If the Co bit is set as logic "0", the transmission of the following information will contain data bytes only.
 - b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic "0", it defines the following data byte as a command. If the D/C# bit is set to logic "1", it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 6) Acknowledge bit will be generated after receiving each control byte or data byte.
- 7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 7-8. The stop condition is established by pulling the "SDA in" from LOW to HIGH while the "SCL" stays HIGH.

Solomon Systech Oct 2008 | P 18/55 | Rev 1.2 | SSD1307

Figure 7-8: Definition of the Start and Stop Condition

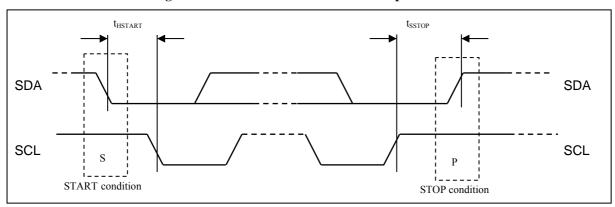
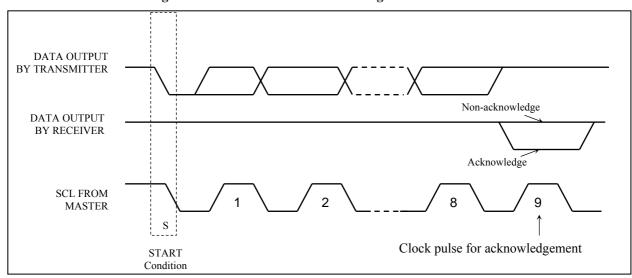


Figure 7-9: Definition of the acknowledgement condition



Please be noted that the transmission of the data bit has some limitations.

- 1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the "HIGH" period of the clock pulse. Please refer to the Figure 7-10 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
- 2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

SDA
SCL
Data line is Stable of data

Figure 7-10: Definition of the data transfer condition

SSD1307 | Rev 1.2 | P 19/55 | Oct 2008 | **Solomon Systech**

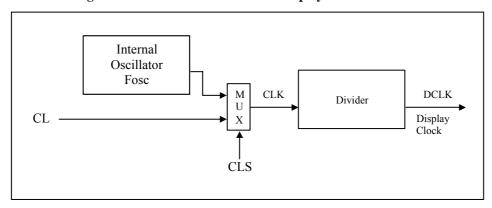
7.2 Command Decoder

This module determines whether the input data is interpreted as data or command. Data is interpreted based upon the input of the D/C# pin.

If D/C# pin is HIGH, D[7:0] is interpreted as display data written to Graphic Display Data RAM (GDDRAM). If it is LOW, the input at D[7:0] is interpreted as a command. Then data input will be decoded and written to the corresponding command register.

7.3 Oscillator Circuit and Display Time Generator

Figure 7-11: Oscillator Circuit and Display Time Generator



This module is an on-chip LOW power RC oscillator circuitry. The operation clock (CLK) can be generated either from internal oscillator or external source CL pin. This selection is done by CLS pin. If CLS pin is pulled HIGH, internal oscillator is chosen and CL should be connected to $V_{\rm SS}$. Pulling CLS pin LOW disables internal oscillator and external clock must be connected to CL pins for proper operation. When the internal oscillator is selected, its output frequency Fosc can be changed by command D5h A[7:4].

The display clock (DCLK) for the Display Timing Generator is derived from CLK. The division factor "D" can be programmed from 1 to 16 by command D5h

$$DCLK = F_{OSC} / D$$

The frame frequency of display is determined by the following formula.

$$F_{FRM} = \frac{F_{osc}}{D \times K \times No. \text{ of Mux}}$$

where

- D stands for clock divide ratio. It is set by command D5h A[3:0]. The divide ratio has the range from 1 to 16.
- K is the number of display clocks per row. The value is derived by

 $K = Phase 1 period + Phase 2 period + K_0$

= 2 + 2 + 50 = 54 at power on reset (that is K_0 is a constant that equals to 50)

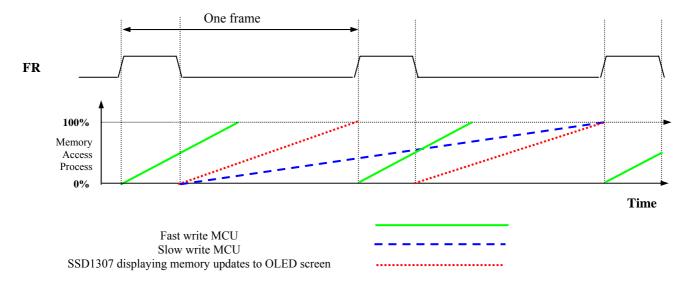
(Please refer to Section 7.6 "Segment Drivers / Common Drivers" for the details of the "Phase")

- Number of multiplex ratio is set by command A8h. The power on reset value is 38 (i.e. 39MUX).
- F_{OSC} is the oscillator frequency. It can be changed by command D5h A[7:4]. The higher the register setting results in higher frequency.

Solomon Systech Oct 2008 | P 20/55 | Rev 1.2 | SSD1307

7.4 FR synchronization

FR synchronization signal can be used to prevent tearing effect.



The starting time to write a new image to OLED driver is depended on the MCU writing speed. If MCU can finish writing a frame image within one frame period, it is classified as fast write MCU. For MCU needs longer writing time to complete (more than one frame but within two frames), it is a slow write one.

For fast write MCU: MCU should start to write new frame of ram data just after rising edge of FR pulse and should be finished well before the rising edge of the next FR pulse.

For slow write MCU: MCU should start to write new frame ram data after the falling edge of the 1st FR pulse and must be finished before the rising edge of the 3rd FR pulse.

7.5 Reset Circuit

When RES# input is LOW, the chip is initialized with the following status:

- 1. Display is OFF
- 2. 128 x 39 Display Mode
- 3. Normal segment and display data column address and row address mapping (SEG0 mapped to address 00h and COM0 mapped to address 00h)
- 4. Shift register data clear in serial interface
- 5. Display start line is set at display RAM address 0
- 6. Column address counter is set at 0
- 7. Normal scan direction of the COM outputs
- 8. Contrast control register is set at 7Fh
- 9. Normal display mode (Equivalent to A4h command)

7.6 Segment Drivers / Common Drivers

Segment drivers deliver 128 current sources to drive the OLED panel. The driving current can be adjusted from 0 to 320uA with 256 steps. Common drivers generate voltage-scanning pulses.

The segment driving waveform is divided into three phases:

- 1. In phase 1, the OLED pixel charges of previous image are discharged in order to prepare for next image content display.
- 2. In phase 2, the OLED pixel is driven to the targeted voltage. The pixel is driven to attain the corresponding voltage level from V_{SS} . The period of phase 2 can be programmed in length from 1 to 15 DCLKs. If the capacitance value of the pixel of OLED panel is larger, a longer period is required to charge up the capacitor to reach the desired voltage.
- 3. In phase 3, the OLED driver switches to use current source to drive the OLED pixels and this is the current drive stage.

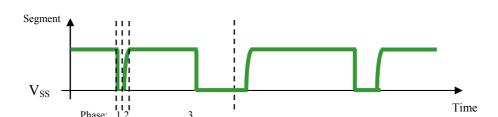


Figure 7-12: Segment Output Waveform in three phases

After finishing phase 3, the driver IC will go back to phase 1 to display the next row image data. This three-step cycle is run continuously to refresh image display on OLED panel.

In phase 3, if the length of current drive pulse width is set to 50, after finishing 50 DCLKs in current drive phase, the driver IC will go back to phase 1 for next row display.

Solomon Systech Oct 2008 | P 22/55 | Rev 1.2 | SSD1307

7.7 Graphic Display Data RAM (GDDRAM)

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128 x 39 bits and the RAM is divided into five pages, from PAGE0 to PAGE4, which are used for monochrome 128x39 dot matrix display, as shown in Figure 7-13.

When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row. For PAGE4, bit D7 is treated as don't care bit.

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

Segment remapping (command A1h) SEG125 SEG126 SEG123 SEG124 Segment re-SEG127 SEGO SEG2 SEG3 SEG mapping (command A0h [RESET]) COM Output Scan COM Output **20L125 20L126 20L124 20L127** Direction **20L123** Scan Direction 200 900 8 8 (command C0h (command C8h) Data [RESET]) Page COM0 D0 COM38 D1 COM1 COM37 COM₂ COM36 D2 D3 СОМЗ COM35 0 COM4 COM34 D4 D5 COM5 COM33 D6 COM6 COM32 D7 COM7 COM31 COM8 COM30 D0 D1 COM9 COM29 D2 COM10 COM28 COM27 D3 COM11 -----D4 COM12 COM26 D5 COM₁₃ COM25 D6 COM14 COM24 COM15 D7 COM23 D0 COM16 COM22 D1 Each box represents one bit COM17 COM21 D2 COM₁₈ COM20 of image data D3 COM₁₉ COM19 2 Π4 COM20 COM18 D5 COM21 COM17 COM16 D6 COM22 D7 COM23 COM15 D0 COM24 COM14 D1 COM13 COM25 COM12 D2 COM₂₆ D3 COM27 COM11 3 D4 COM28 COM10 COM29 COM9 D5 D6 COM30 COM8 D7 COM31 COM7 COM6 COM32 D0 D1 COM33 COM5 D2 COM34 COM4 4 COM35 COM3 D3 D4 COM36 COM2 D5 COM37 COM1 D6 COM38 COM0 Don't care bit D7

Figure 7-13: GDDRAM pages structure of SSD1307

7.8 SEG/COM Driving block

This block is used to derive the incoming power sources into the different levels of internal use voltage and current.

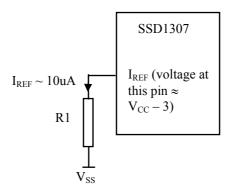
- V_{CC} is the most positive voltage supply.
- V_{COMH} is the Common deselected level. It is internally regulated.
- V_{LSS} is the ground path of the analog and panel current.
- I_{REF} is a reference current source for segment current drivers I_{SEG}. The relationship between reference current and segment current of a color is:

$$I_{SEG} = (Contrast+1) / 8 \times I_{REF}$$

in which the contrast (0~255) is set by Set Contrast command

The magnitude of I_{REF} is controlled by the value of resistor, which is connected between I_{REF} pin and Vss as shown in Figure 7-14. It is recommended to set I_{REF} to $10 \pm 2uA$ so as to achieve $I_{SEG} = 320uA$ at maximum contrast 255.

Figure 7-14: I_{REF} Current Setting by Resistor Value



Since the voltage at I_{REF} pin is $V_{CC} - 3V$, the value of resistor R1 can be found as below:

For
$$I_{REF} = 10uA$$
, $V_{CC} = 12V$:

$$\begin{split} R1 &= (Voltage~at~I_{REF} - V_{SS}) \, / \, I_{REF} \\ &\approx (12-3) \, / \, 10uA \\ &= 900k\Omega \end{split}$$

Solomon Systech Oct 2008 | P 24/55 | Rev 1.2 | SSD1307

7.9 Power ON and OFF sequence

The following figures illustrate the recommended power ON and power OFF sequence of SSD1307

Power ON sequence:

- 1. Power ON V_{DD}
- 2. After V_{DD} become stable, set RES# pin LOW (logic low) for at least 3us (t₁) ⁽³⁾ and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON V_{CC} ⁽¹⁾
- 4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).

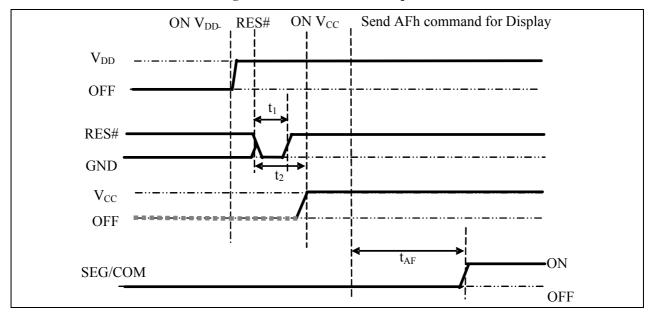


Figure 7-15: The Power ON sequence

Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF $V_{CC}^{(1),(2)}$
- 3. Power OFF V_{DD} after t_{OFF} . (4) (typical t_{OFF} =100ms)

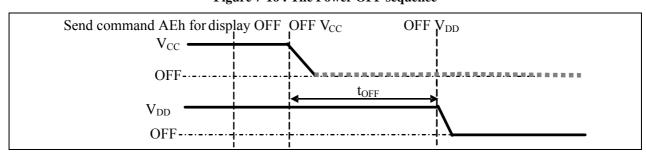


Figure 7-16: The Power OFF sequence

Note:

(1) V_{CC} should be kept float (i.e. disable) when it is OFF.

⁽²⁾ Power Pins (V_{DD}, V_{CC}) can never be pulled to ground under any circumstance.

 $^{(3)}$ The register values are reset after t_1 .

 $^{(4)}$ V_{DD} should not be Power OFF before V_{CC} Power OFF.

8 Command Table

Table 8-1: Proposed SSD1307 Command Table

(R/W#(WR#) = 0, E(RD#) = 1 unless specific setting is stated)

1. Fu	ndament	al Co	mmai	nd Ta	ble						
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	81	1	0	0	0	0	0	0	1	Set Contrast	Double byte command to select 1 out of 256 contrast
0	A[7:0]	A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0	Control	steps. Contrast increases as the value increases.
											(RESET = 7Fh)
0	A4/A5	1	0	1	0	0	1	0	X_0	Entire Display	A4h, X_0 =0b: Resume to RAM content display (RESET)
										ON	Output follows RAM content
											A5h, X_0 =1b: Entire display ON
											Output ignores RAM content
0	A6/A7	1	0	1	0	0	1	1	X_0	Set	A6h, X[0]=0b: Normal display (RESET)
										Normal/Inverse	0 in RAM: OFF in display panel
										Display	1 in RAM: ON in display panel
											A7h, X[0]=1b: Inverse display
											0 in RAM: ON in display panel
											1 in RAM: OFF in display panel
0	AΕ	1	0	1	0	1	1	1	X_0	Set Display	AEh, X[0]=0b:Display OFF (sleep mode) (RESET)
	AF									ON/OFF	AFh X[0]=1b:Display ON in normal mode

2. \$	Scrolling C	omn	and	Tab	le						
D/ 0	C# Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description
0	26/27	0	0	1	0	0	1	1	X_0	Continuous	26h, X[0]=0, Right Horizontal Scroll
0	A[7:0]	0	0	0	0	0	0	0	0	Horizontal	27h, X[0]=1, Left Horizontal Scroll
0	B[2:0]	*	*	*	*	*	B_2	B_1	B_{0}	Scroll Setup	(Horizontal scroll by 1 column)
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0		A[7:0] : Dummy byte (Set as 00h)
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0		[1[7.0]. Builing Oyle (Set us von)
0	E[7:0]	0	0	0	0	0	0	0	0		B[2:0] : Define start page address
0	F[7:0]	1	1	1	1	1	1	1	1		000b – PAGE0 011b – PAGE3 110b – invalid
											001b – PAGE1 100b – PAGE4 111b – invalid
											010b – PAGE2 101b – invalid
											C[2:0] : Set time interval between each scroll step in terms of frame frequency 000b - 5 frames 100b - 3 frames 001b - 64 frames 101b - 4 frames 010b - 128 frames 110b - 25 frame 011b - 256 frames 111b - 2 frame D[2:0] : Define end page address 000b - PAGE0 011b - PAGE3 110b - invalid 001b - PAGE1 100b - PAGE4 111b - invalid 010b - PAGE2 101b - invalid The value of D[2:0] must be larger or equal to B[2:0] E[7:0] : Dummy byte (Set as 00h) F[7:0] : Dummy byte (Set as FFh)

 Solomon Systech
 Oct 2008
 P 26/55
 Rev 1.2
 SSD1307

2. S c	rolling C	omm	and	Tab	le						
D/C	#Hex			D5		D3	D2	D1	D0	Command	Description
0	29/2A	0	0	1	0	1	0	X_1	X_0	Continuous	29h, X ₁ X ₀ =01b : Vertical and Right Horizontal
0	A[2:0]	0	0	0	0	0	0	0		Vertical and	Scroll
0	B[2:0]	*	*	*	*	*	B_2	B_1		Horizontal	
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0	Scroll Setup	2Ah, $X_1X_0=10b$: Vertical and Left Horizontal
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0		Scroll
0	E[5:0]	*	*	E_5	E_4	E_3	E_2	E_1	E_0		(Horizontal scroll by 1 column)
											A[7:0]: Dummy byte (Set as 00h)
											A[7.0]. Duffilly byte (Set as 00h)
											B[2:0] : Define start page address
											000b – PAGE0 011b – PAGE3 110b – invalid
											001b – PAGE1 100b – PAGE4 111b –invalid
											010b – PAGE2 101b – invalid
											C[2:0] . Set time internal between each corell
											C[2:0] : Set time interval between each scroll step in terms of frame frequency
											000b - 5 frames 100b - 3 frames
											001b – 64 frames 101b – 4 frames
											010b – 128 frames 110b – 25 frame
											011b – 256 frames 111b – 2 frame
											D[2:0] : Define end page address
											000b - PAGE0 011b - PAGE3 110b - invalid
											001b - PAGE1 100b - PAGE4 111b - invalid
											010b – PAGE2 101b – invalid
											The value of D[2:0] must be larger or equal
											to B[2:0]
											E[5:0] . Ventical conciling affect
											E[5:0] : Vertical scrolling offset e.g. E[5:0]= 01h refer to offset =1 row
											E[5:0] = 26h refer to offset = 38 rows
											E[3.0] Zon teter to onset 30 tows
											Note
											(1) No continuous vertical scrolling is available.
0	2E	0	0	1	0	1	1	1	0	Deactivate	Stop scrolling that is configured by command
										scroll	26h/27h/29h/2Ah.
											Note
											(1) After sending 2Eh command to deactivate the
											scrolling action, the ram data needs to be rewritten.
0	2F	0	0	1	0	1	1	1	1	Activate scroll	Start scrolling that is configured by the
											scrolling setup commands :26h/27h/29h/2Ah
											with the following valid sequences:
											Walid command acqueres 1: 26h :2Eh
											Valid command sequence 1: 26h;2Fh. Valid command sequence 2: 27h;2Fh.
											Valid command sequence 3: 29h; 2Fh.
											Valid command sequence 4: 2Ah; 2Fh.
											For example, if "26h; 2Ah; 2Fh." commands
											are issued, the setting in the last scrolling setup
											command, i.e. 2Ah in this case, will be
											executed. In other words, setting in the last
											scrolling setup command overwrites the setting
											in the previous scrolling setup commands.

SSD1307 Rev 1.2 P 27/55 Oct 2008 **Solomon Systech**

2. S c	rolling C	omn	and	Tab	le						
D/C	#Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	A3	1	0	1	0	0	0	1	1	Set Vertical	A[5:0]: Set No. of rows in top fixed area. The
0	A[5:0]	*	*	A_5	A_4	A_3	A_2	\mathbf{A}_1	A_0	Scroll Area	No. of rows in top fixed area is
0	B[5:0]	*	*	B_5	B_4	B_3	B_2	B_1	B_0		referenced to the top of the
											GDDRAM (i.e. row 0).[RESET = $0d$]
											B[5:0]: Set No. of rows in scroll area. This is
											the number of rows to be used for
											vertical scrolling. The scroll area
											starts in the first row below the top
											fixed area. [RESET = 39d]
											Note
											$^{(1)}$ A[5:0]+B[5:0] <= MUX ratio
											⁽²⁾ B[5:0] <= MUX ratio ^(3a) Vertical scrolling offset (E[5:0] in 29h/2Ah) <
											B[5:0]
											(3b) Set Display Start Line (X5X4X3X2X1X0 of
											40h~66h) < B[5:0]
											(4) The last row of the scroll area shifts to the first
											row of the scroll area.
											(5) For 39d MUX display
											A[5:0] = 0, B[5:0]=39 : whole area scrolls A[5:0]= 0, B[5:0] < 39 : top area scrolls
											A[5.0] = 0, $B[5.0] < 39$: top area serons A[5:0] + B[5:0] < 39: central area scrolls
											A[5:0] + B[5:0] = 39: bottom area scrolls

3. A d	. Addressing Setting Command Table													
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description			
0	00~0F	0	0	0	0	X ₃	X ₂	X ₁		Start Address for Page Addressing Mode	Set the lower nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET. Note (1) This command is only for page addressing mode.			
0	10~17	0	0	0	1	0	X ₂	X ₁			Set the higher nibble of the column start address register for Page Addressing Mode using X[2:0] as data bits. The initial display line register is reset to 0000b after RESET. Note (1) This command is only for page addressing mode.			
0	20 A[1:0]	0 *	0 *	1 *	0 *	0 *	0 *	0 A ₁			A[1:0] = 00b, Horizontal Addressing Mode A[1:0] = 01b, Vertical Addressing Mode A[1:0] = 10b, Page Addressing Mode (RESET) A[1:0] = 11b, Invalid			

 Solomon Systech
 Oct 2008
 P 28/55
 Rev 1.2
 SSD1307

3.	Addressin	ig Set	tting	Com	man	d Tal	ble				
D	/C#Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description
0	21	0	0	1	0	0	0	0	_	Set Column	Setup column start and end address
0	A[6:0] B[6:0]	*	$egin{array}{c} A_6 \ B_6 \end{array}$	A ₅ B ₅	A_4 B_4	A_3 B_3	$egin{array}{c} A_2 \ B_2 \end{array}$	A_1 B_1	$egin{array}{c} A_0 \ B_0 \end{array}$	Address	A[6:0]: Column start address, range: 0-127d, (RESET=0d)
											B[6:0]: Column end address, range : 0-127d, (RESET =127d)
											Note (1) This command is only for horizontal or vertical addressing mode.
0	22	0	0	1	0	0	0	1	0	Set Page Address	Setup page start and end address
0	A[2:0] B[2:0]	*	*	*	*	*	$egin{array}{c} A_2 \ B_2 \end{array}$	A_1 B_1	$egin{array}{c} A_0 \ B_0 \end{array}$		A[2:0]: Page start Address, range: 0-4d, (RESET = 0d)
											B[2:0] : Page end Address, range : 0-4d, (RESET = 4d)
											Note
											(1) This command is only for horizontal or vertical addressing mode.
0	B0~B4	1	0	1	1	0	X_2	X_1	X_0		tSet GDDRAM Page Start Address
										Address for Page Addressing Mode	(PAGE0~PAGE4) for Page Addressing Mode using X[2:0].
											Note
											(1) This command is only for page addressing mode.

4. H	Hardware Configuration (Panel resolution & layout related) Command Table											
D/C	#Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description	
0	40~66	0	1	X_5	X_4	X_3	X_2	X_1	X_0	Set Display Start	Set display RAM display offset from 0d-38d	
										Line	using $X_5X_4X_3X_2X_1X_0$.	
											Display offset is reset to 000000b during	
ļ											RESET.	
0	A0/A1	1	0	1	0	0	0	0	X_0	Set Segment Re-	A0h, X[0]=0b: column address 0 is mapped to	
										map	SEG0 (RESET)	
											A1h, X[0]=1b: column address 127 is mapped	
ļ											to SEG0	
0	A8	1	0	1	0	1	0	0	0	Set Multiplex	Set MUX ratio to N+1 MUX	
0	A[5:0]	*	*	A_5	A_4	A_3	A_2	A_1	A_0	Ratio	N=A[5:0] : from 16MUX to 39MUX, RESET=	
											100110b (i.e.38d, 39Mux)	
ļ											A[5:0] from 0 to 14 are invalid entry.	
0	C0/C8	1	1	0	0	X_3	0	0	0	Set COM Output	C0h, X[3]=0b: normal mode (RESET) Scan	
										Scan Direction	from COM0 to COM[N –1]	
											C8h, X[3]=1b: remapped mode. Scan from	
											COM[N-1] to COM0	
											Where N is the Multiplex ratio.	
0	D3	1	1	0	1	0	0	1	1	Set Display Offset	Set vertical shift by COM from 0d~38d.	
0	A[5:0]	*	*	A_5	A_4	A_3	A_2	\mathbf{A}_1	A_0		The value is reset to 00h after RESET.	

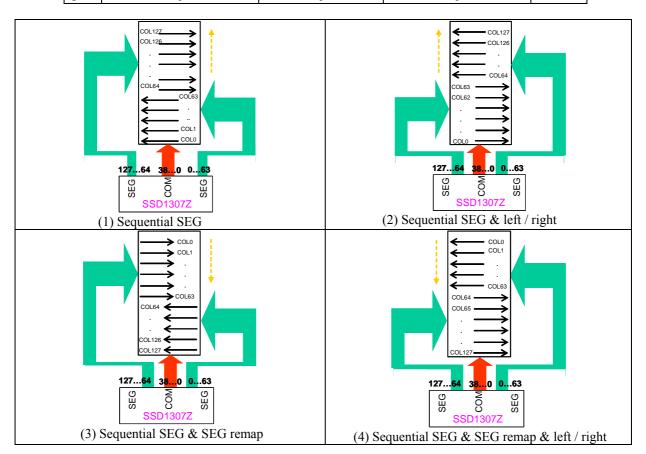
SSD1307 Rev 1.2 P 29/55 Oct 2008 **Solomon Systech**

4. H a	Hardware Configuration (Panel resolution & layout related) Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description	
0	DA	1	1	0	1	1	0	1	0	Set SEG Pins	A[4]=0b, Sequential SEG pin configuration	
0	A[5:4]	0	0	A_5	A_4	0	0	1		Hardware	A[4]=1b(RESET), Alternative (odd/even) SEG	
										Configuration	pin configuration	
											A[5]=0b(RESET), Disable SEG Left/Right	
											remap	
											A[5]=1b, Enable SEG Left/Right remap	

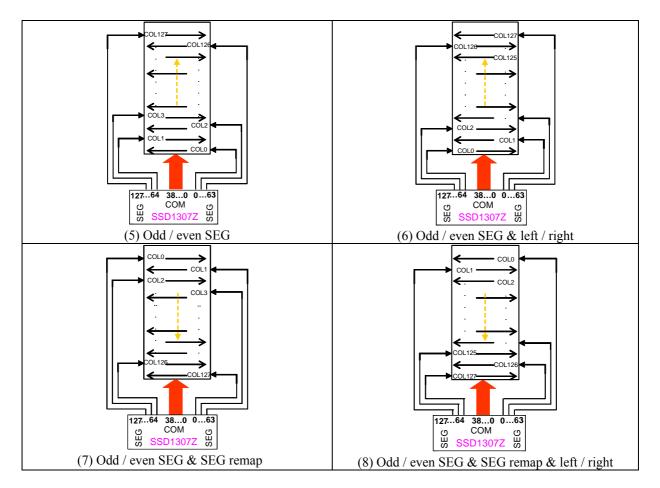
Table 8-2: SEG Pins Hardware Configuration

SEG Odd / Even (Left / Right) and Top / Bottom connections are software selectable, thus there are total of 8 cases and they are shown on the followings,

<i>J</i>				
Case	Oddeven (1) / Sequential (0)	SEG Remap	Left / Right Swap	Remark
no.	Command : DAh -> A[4]	Command: A0h / A1h	Command: DAh -> A[5]	
1	0	0	0	
2	0	0	1	
3	0	1	0	
4	0	1	1	
5	1	0	0	Default
6	1	0	1	
7	1	1	0	
8	1	1	1	



 Solomon Systech
 Oct 2008
 P 30/55
 Rev 1.2
 SSD1307



Note:

(1) The above eight figures are all with bump pads being faced up.

5. Ti	ming &	Driv	ving s	schen	ne Se	tting	Com	ıman	d Ta	ble	
	D/C#Hex		D6	D5		D3		D1	_	Command	Description
0	D5 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	0 A ₃	1	0 A ₁	1 A ₀		A[3:0]: Define the divide ratio (D) of the display clocks (DCLK): Divide ratio= A[3:0] + 1, RESET is 0001b (divide ratio = 2) A[7:4]: Set the Oscillator Frequency, F _{OSC} . Oscillator Frequency increases with the value of A[7:4] and vice versa. RESET is 1100b Range:0000b~1111b Frequency increases as setting value increases.
0	D9 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	1 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Pre-charge Period	A[3:0]: Phase 1 period of up to 15 DCLK clocks. 0 is invalid entry (RESET=2h) A[7:4]: Phase 2 period of up to 15 DCLK clocks .0 is invalid entry (RESET=2h)
0	DB A[6:4]	1 0	1 A ₆	0 A ₅	1 A ₄	1 0	0 0	1 0		Set V _{COMH} Deselect Level	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

SSD1307 Rev 1.2 P 31/55 Oct 2008 **Solomon Systech**

6. Ot	hers										
D/C #	Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description
0	E3	1	1	1	0	0	0	1	1	NOP	Command for no operation

Note

(1) "*" stands for "Don't care".

 Solomon Systech
 Oct 2008
 P 32/55
 Rev 1.2
 SSD1307

Table 8-3: Read Command Table

Bit Pattern	Command	Descri	ption
$D_7D_6D_5D_4D_3D_2D_1D_0$	Status Register Read	D[7]:	Reserved
		D[6]:	"1" for display OFF / "0" for display ON
		D[5]	Reserved
		D[4] :	Reserved
		D[3] :	Reserved
		D[2] :	Reserved
		D[1] :	Reserved
		D[0]:	Reserved

Note

8.1 Data Read / Write

To read data from the GDDRAM, select HIGH for both the R/W# (WR#) pin and the D/C# pin for 6800-series parallel mode and select LOW for the E (RD#) pin and HIGH for the D/C# pin for 8080-series parallel mode. No data read is provided in serial mode operation.

In normal data read mode the GDDRAM column address pointer will be increased automatically by one after each data read.

Also, a dummy read is required before the first data read.

To write data to the GDDRAM, select LOW for the R/W# (WR#) pin and HIGH for the D/C# pin for both 6800-series parallel mode and 8080-series parallel mode. The serial interface mode is always in write mode. The GDDRAM column address pointer will be increased automatically by one after each data write.

Table 8-4: Address increment table (Automatic)

D/C#	R/W# (WR#)	Comment	Address Increment
0	0	Write Command	No
0	1	Read Status	No
1	0	Write Data	Yes
1	1	Read Data	Yes

SSD1307 | Rev 1.2 | P 33/55 | Oct 2008 | **Solomon Systech**

⁽¹⁾ Patterns other than those given in the Command Table are prohibited to enter the chip as a command; as unexpected results can occur.

9 COMMAND DESCRIPTIONS

9.1 Fundamental Command

9.1.1 Set Lower Column Start Address for Page Addressing Mode (00h~0Fh)

This command specifies the lower nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 8-1 and Section 9.1.3 for details.

9.1.2 Set Higher Column Start Address for Page Addressing Mode (10h~17h)

This command specifies the higher nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 8-1 and Section 9.1.3 for details.

9.1.3 Set Memory Addressing Mode (20h)

There are 3 different memory addressing mode in SSD1307: page addressing mode, horizontal addressing mode and vertical addressing mode. This command sets the way of memory addressing into one of the above three modes. In there, "COL" means the graphic display data RAM column.

Page addressing mode (A[1:0]=10xb)

In page addressing mode, after the display RAM is read / written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is not changed. Users have to set the new page and column addresses in order to access the next page RAM content. The sequence of movement of the PAGE and column address point for page addressing mode is shown in Figure 9-1.

 COL0
 COL 1

 COL 126
 COL 127

 PAGE0
 Image: Color of the page of

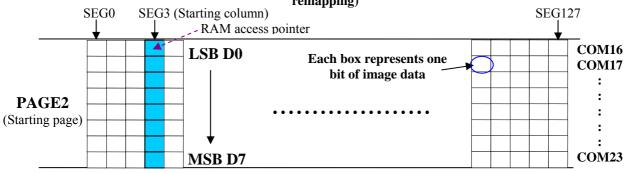
Figure 9-1: Address Pointer Movement of Page addressing mode

In normal display data RAM read or write and page addressing mode, the following steps are required to define the starting RAM access pointer location:

- Set the page start address of the target display location by command B0h to B4h.
- Set the lower start column address of pointer by command 00h~0Fh.
- Set the upper start column address of pointer by command 10h~17h.

For example, if the page address is set to B2h, lower column address is 03h and upper column address is 10h, then that means the starting column is SEG3 of PAGE2. The RAM access pointer is located as shown in Figure 9-2. The input data byte will be written into RAM position of column 3.

Figure 9-2: Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-remapping)



Solomon Systech Oct 2008 | P 34/55 | Rev 1.2 | SSD1307

Horizontal addressing mode (A[1:0]=00b)

In horizontal addressing mode, after the display RAM is read / written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is increased by 1. The sequence of movement of the page and column address point for horizontal addressing mode is shown in Figure 9-3. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 9-3.)

PAGE0
PAGE1
PAGE2
PAGE3
PAGE4
PAGE4

COL 1 COL 126 COL 127

COL 126 COL 127

PAGE 1
PAGE 2
PAGE 3
PAGE 4

Figure 9-3: Address Pointer Movement of Horizontal addressing mode

Vertical addressing mode: (A[1:0]=01b)

In vertical addressing mode, after the display RAM is read / written, the page address pointer is increased automatically by 1. If the page address pointer reaches the page end address, the page address pointer is reset to page start address and column address pointer is increased by 1. The sequence of movement of the page and column address point for vertical addressing mode is shown in Figure 9-4. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 9-4.)

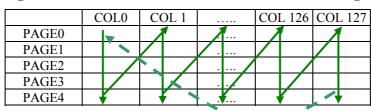


Figure 9-4: Address Pointer Movement of Vertical addressing mode

In normal display data RAM read or write and horizontal / vertical addressing mode, the following steps are required to define the RAM access pointer location:

- Set the column start and end address of the target display location by command 21h.
- Set the page start and end address of the target display location by command 22h.

Example is shown in Figure 9-5.

9.1.4 Set Column Address (21h)

This triple byte command specifies column start address and end address of the display data RAM. This command also sets the column address pointer to column start address. This pointer is used to define the current read/write column address in graphic display data RAM. If horizontal address increment mode is enabled by command 20h, after finishing read/write one column data, it is incremented automatically to the next column address. Whenever the column address pointer finishes accessing the end column address, it is reset back to start column address and the row address is incremented to the next row.

SSD1307 | Rev 1.2 | P 35/55 | Oct 2008 | **Solomon Systech**

9.1.5 Set Page Address (22h)

This triple byte command specifies page start address and end address of the display data RAM. This command also sets the page address pointer to page start address. This pointer is used to define the current read/write page address in graphic display data RAM. If vertical address increment mode is enabled by command 20h, after finishing read/write one page data, it is incremented automatically to the next page address. Whenever the page address pointer finishes accessing the end page address, it is reset back to start page address.

The figure below shows the way of column and page address pointer movement through the example: column start address is set to 2 and column end address is set to 97, page start address is set to 1 and page end address is set to 2; Horizontal address increment mode is enabled by command 20h. In this case, the graphic display data RAM column accessible range is from column 2 to column 97 and from page 1 to page 2 only. In addition, the column address pointer is set to 2 and page address pointer is set to 1. After finishing read/write one pixel of data, the column address is increased automatically by 1 to access the next RAM location for next read/write operation (*solid line in Figure 9-5*). Whenever the column address pointer finishes accessing the end column 97, it is reset back to column 2 and page address is automatically increased by 1 (*solid line in Figure 9-5*). While the end page 2 and end column 97 RAM location is accessed, the page address is reset back to 1 and the column address is reset back to 2 (*dotted line in Figure 9-5*).

 Col 0
 Col 1
 Col 2

 Col 97
 Col 98

 Col 126
 Col 127

 PAGE0
 PAGE1
 PAGE2
 PAGE3
 PAGE4
 PAGE4
 PAGE4
 PAGE4
 PAGE4
 PAGE4
 PAGE4
 PAGE3
 PAGE4
 PAGE4

Figure 9-5: Example of Column and Row Address Pointer Movement

9.1.6 Set Display Start Line (40h~66h)

This command sets the Display Start Line register to determine starting address of display RAM, by selecting a value from 0 to 38. With value equal to 0, RAM row 0 is mapped to COM0. With value equal to 1, RAM row 1 is mapped to COM0 and so on.

Refer to Table 9-1 for more illustrations.

9.1.7 Set Contrast Control for BANK0 (81h)

This command sets the Contrast Setting of the display. The chip has 256 contrast steps from 00h to FFh. The segment output current increases as the contrast step value increases.

9.1.8 Set Segment Re-map (A0h/A1h)

This command changes the mapping between the display data column address and the segment driver. It allows flexibility in OLED module design. Please refer to Table 8-2.

This command only affects subsequent data input. Data already stored in GDDRAM will have no changes.

Solomon Systech Oct 2008 | P 36/55 | Rev 1.2 | SSD1307

9.1.9 Entire Display ON (A4h/A5h)

A4h command enable display outputs according to the GDDRAM contents.

If A5h command is issued, then by using A4h command, the display will resume to the GDDRAM contents. In other words, A4h command resumes the display from entire display "ON" stage.

A5h command forces the entire display to be "ON", regardless of the contents of the display data RAM.

9.1.10 Set Normal/Inverse Display (A6h/A7h)

This command sets the display to be either normal or inverse. In normal display a RAM data of 1 indicates an "ON" pixel while in inverse display a RAM data of 0 indicates an "ON" pixel.

9.1.11 Set Multiplex Ratio (A8h)

This command switches the default 39 multiplex mode to any multiplex ratio, ranging from 16 to 39. The output pads COM0~COM38 will be switched to the corresponding COM signal.

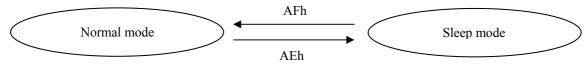
9.1.12 Set Display ON/OFF (AEh/AFh)

These single byte commands are used to turn the OLED panel display ON or OFF.

When the display is ON, the selected circuits by Set Master Configuration command will be turned ON. When the display is OFF, those circuits will be turned OFF and the segment and common output are in V_{SS} state and high impedance state, respectively. These commands set the display to one of the two states:

AEh : Display OFFAFh : Display ON

Figure 9-6: Transition between different modes



9.1.13 Set Page Start Address for Page Addressing Mode (B0h~B4h)

This command positions the page start address from 0 to 4 in GDDRAM under Page Addressing Mode. Please refer to Table 8-1 and Section 9.1.3 for details.

SSD1307 | Rev 1.2 | P 37/55 | Oct 2008 | **Solomon Systech**

9.1.14 Set COM Output Scan Direction (C0h/C8h)

This command sets the scan direction of the COM output, allowing layout flexibility in the OLED module design. Additionally, the display will show once this command is issued. For example, if this command is sent during normal display, then the graphic display will be vertically flipped immediately. Please refer to Figure 9-7 and Table 9-2 for details.

SEG2 SEG0 SEG2 SEG0 SEG1 SEG3. SEG1 SEG3 SSD1307 SSD1307 Row 0 maps to COM0 pin

Figure 9-7: Example of row address mapping

Row 38 maps to COM0 pin

9.1.15 Set Display Offset (D3h)

This is a double byte command. The second command specifies the mapping of the display start line to one of COM0~COM38 (assuming that COM0 is the display start line then the display start line register is equal to 0).

For example, to move the COM4 towards the COM0 direction by 4 lines the 6-bit data in the second byte should be given as 000100b. To move in the opposite direction by 4 lines the 6-bit data should be given by 39 – 4, so the second byte would be 100011b. The following two tables (Table 9-1, Table 9-2) show the examples of setting the command C0h/C8h and D3h.

Solomon Systech Oct 2008 P 38/55 Rev 1.2 SSD1307

Table 9-1: Example of Set Display Offset and Display Start Line without Remap

Set MUX ration (A8h) COM normal / remap (C0h / C8h) Normal Norma Normal Normal Normal Normal Hardware Display offset (D3h) Display start line (40h - 66h) COM RAM² ₹OW∠ COM1 ROW1 ROW1 ROW1 COM₂ ROW2 RAM2 ROW6 RAM6 ROW2 RAM6 ROW2 RAM2 ROW6 RAM6 ROW2 RAM6 COM3 ROW3 RAM3 ROW7 RAM7 ROW3 RAM7 ROW3 RAM3 ROW7 RAM7 ROW3 RAM7 COM4 ROW4 RAM4 ROW8 RAM8 ROW4 RAM8 ROW4 RAM4 ROW8 RAM8 ROW4 RAM8 COM5 RAM5 RAM9 RAM9 RAM5 RAM9 ROW5 ROW5 ROW9 ROW5 ROW5 ROW9 RAM9 COM6 COM7 RAM10 RAM11 ROW6 RAM6 ROW10 ROW6 RAM10 ROW6 RAM6 ROW10 RAM10 ROW6 RAM10 ROW7 RAM7 ROW11 ROW7 RAM11 ROW7 RAM7 ROW11 RAM11 ROW7 RAM11 COM8 ROW8 RAMA ROW12 RAM12 ROW8 RAM12 ROW8 RAMA ROW12 RAM12 ROW8 RAM12 COM9 ROW9 RAM9 ROW13 RAM13 ROW9 RAM13 ROW9 RAM9 ROW13 RAM13 ROW9 RAM13 RAM10 RAM11 COM₁₀ ROW10 ROW14 RAM14 ROW10 RAM14 ROW10 RAM10 ROW14 RAM14 ROW10 RAM14 COM11 ROW11 ROW15 RAM15 ROW11 RAM11 ROW15 RAM15 RAM15 ROW11 RAM15 ROW11 COM12 COM13 RAM12 RAM13 RAM16 RAM17 ROW12 ROW13 ROW12 ROW16 ROW12 RAM16 RAM12 ROW16 RAM16 ROW12 RAM16 ROW13 RAM17 RAM13 ROW17 RAM17 RAM17 ROW13 ROW17 ROW13 COM14 ROW14 RAM14 ROW18 RAM18 ROW14 RAM18 ROW14 RAM14 ROW18 RAM18 ROW14 RAM18 COM15 ROW15 RAM15 ROW19 RAM19 ROW15 RAM19 ROW15 RAM15 ROW19 RAM19 ROW15 RAM19 COM16 COM17 RAM20 RAM21 ROW16 RAM16 ROW20 ROW16 RAM20 ROW16 RAM16 BOW 20 RAM20 ROW16 RAM20 RAM21 RAM17 ROW21 RAM21 RAM21 ROW21 ROW17 RAM17 ROW17 ROW17 ROW17 COM18 COM19 ROW18 ROW19 RAM18 RAM19 ROW22 ROW23 RAM22 RAM23 RAM22 ROW22 ROW23 RAM22 RAM23 ROW18 ROW19 RAM22 RAM23 ROW18 ROW18 RAM18 RAM23 RAM19 ROW19 ROW19 COM20 COM21 RAM24 RAM25 ROW20 ROW20 RAM20 ROW24 ROW20 RAM24 ROW20 RAM20 ROW24 RAM24 RAM24 RAM25 RAM25 RAM21 ROW21 RAM21 ROW25 ROW21 ROW21 ROW25 ROW21 RAM25 COM22 COM23 RAM26 RAM27 RAM22 RAM23 RAM26 RAM27 RAM26 RAM27 ROW22 RAM22 ROW26 ROW22 RAM26 ROW22 ROW26 ROW22 RAM23 RAM27 ROW27 ROW23 ROW27 ROW23 ROW23 ROW23 COM24 COM25 RAM24 RAM25 RAM28 RAM29 RAM28 RAM29 RAM28 RAM29 RAM28 RAM29 ROW24 ROW28 ROW24 ROW24 RAM24 ROW28 ROW24 RAM25 ROW25 ROW29 ROW25 ROW29 ROW25 ROW25 COM26 ROW26 RAM26 ROW30 RAM30 ROW26 RAM30 ROW26 RAM26 ROW30 RAM30 ROW26 RAM30 RAM27 RAM31 RAM27 RAM31 COM27 ROW27 ROW31 RAM31 ROW27 ROW27 ROW31 RAM31 ROW27 COM28 ROW28 RAM28 RAM32 ROW28 RAM32 ROW28 RAM28 ROW28 RAM32 COM29 ROW29 RAM29 ROW33 RAM33 ROW29 RAM33 ROW29 RAM29 ROW29 RAM33 COM30 ROW30 RAM30 RAM34 ROW30 RAM34 RAM30 ROW30 RAM34 COM31 RAM35 RAM35 ROW31 RAM31 ROW35 ROW31 ROW31 RAM31 ROW31 RAM35 COM32 ROW32 RAM32 RAM36 ROW32 RAM36 COM33 ROW33 RAM33 ROW37 RAM37 ROW33 RAM37 COM34 ROW34 RAM34 RAM38 ROW34 RAM38 ROW38 COM35 ROW35 RAM35 ROW0 RAMO ROW35 RAMO ROWO RAMO COM36 ROW36 RAM36 ROW1 ROW36 RAM1 ROW1 RAM1 COM37 ROW37 RAM37 ROW2 RAM2 ROW37 RAM2 ROW2 RAM2 ROW38 (d) (f) (c) (e) examples

SOLOMON SOLOMON SOLOMON SOLOMON SYSTECH SYSTECH SYSTECH (a) (b) (c) (d) / SOLOMON SOLOMON SOLOMON SYSTECH SYSTECH

(f)

(e)

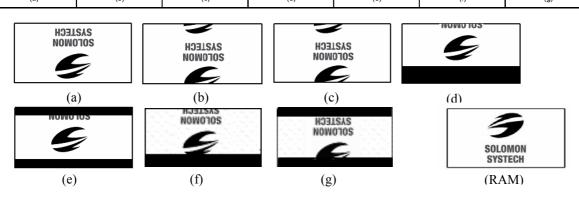
SSD1307 | Rev 1.2 | P 39/55 | Oct 2008 | **Solomon Systech**

(RAM)

Table 9-2: Example of Set Display Offset and Display Start Line with Remap

Remap Remap Remap Remap Remap Remap Remap Hardware pın nam RAM 3 RAM ROW38 RAM3 RAM3 RAM35 ROW38 ROW: ROW3 ROW3 COM0 RAM2 RAM1 RAM2 RAM1 ROW30 RAM34 RAM33 RAM29 COM2 ROW36 RAM36 ROW1 ROW36 ROW29 ROW29 СОМЗ ROW35 RAM35 ROW0 RAM0 ROW35 RAM0 ROW28 RAM28 ROW28 RAM32 COM4 ROW34 RAM34 ROW38 RAM38 ROW34 RAM38 ROW27 RAM27 ROW31 RAM31 ROW27 RAM31 ROW31 RAM0 RAM37 RAM36 RAM37 RAM36 RAM30 RAM29 RAM38 RAM37 RAM26 ROW30 RAM30 ROW30 RAM36 RAM25 RAM29 COM6 ROW32 RAM32 ROW32 ROW25 ROW29 ROW25 ROW29 COM7 ROW31 RAM31 RAM35 RAM35 ROW31 RAM35 ROW24 RAM24 ROW28 RAM28 ROW24 RAM28 ROW28 RAM36 RAM34 RAM34 RAM27 RAM27 COM8 ROW30 RAM30 ROW30 RAM34 ROW23 RAM23 ROW27 ROW23 ROW27 RAM35 COM9 ROW29 RAM29 RAM33 RAM33 ROW29 RAM33 ROW22 RAM22 ROW26 RAM26 ROW22 RAM26 ROW26 RAM34 RAM25 COM₁₀ RAM32 RAM32 RAM32 RAM21 RAM25 ROW28 RAM28 ROW28 ROW21 ROW25 ROW21 ROW25 RAM33 COM11 COM12 RAM31 RAM30 RAM31 RAM30 RAM31 RAM30 RAM20 RAM19 RAM24 RAM23 RAM24 RAM23 RAM32 RAM31 ROW27 RAM27 ROW27 ROW20 ROW24 ROW20 ROW24 RAM26 ROW26 ROW26 ROW19 ROW23 ROW19 ROW23 RAM22 COM13 ROW25 RAM25 RAM29 RAM29 ROW25 RAM29 ROW18 RAM18 ROW22 RAM22 ROW18 ROW22 RAM30 COM14 RAM28 RAM28 RAM28 RAM21 RAM21 ROW24 RAM24 ROW24 ROW17 RAM17 ROW21 ROW17 ROW21 RAM29 COM15 COM16 RAM27 RAM26 RAM27 RAM26 RAM27 RAM26 RAM16 RAM15 RAM20 RAM19 RAM20 RAM19 RAM28 RAM27 RAM23 ROW23 ROW16 ROW20 ROW16 ROW20 ROW23 RAM22 ROW22 ROW22 **ROW15 ROW19** ROW15 **ROW19** COM17 ROW21 RAM21 RAM25 RAM25 ROW21 RAM25 ROW14 RAM14 ROW18 RAM18 ROW14 RAM18 ROW18 RAM26 COM18 ROW20 RAM20 RAM24 RAM24 ROW20 RAM24 ROW13 RAM13 ROW17 RAM17 ROW13 RAM17 ROW17 RAM25 RAM16 RAM15 RAM16 COM19 ROW19 RAM19 RAM23 RAM23 ROW19 RAM23 ROW12 RAM12 ROW16 ROW12 ROW16 RAM24 RAM22 RAM15 RAM22 COM20 ROW18 RAM18 ROW18 RAM22 RAM11 RAM23 ROW11 ROW15 ROW11 ROW15 COM21 ROW17 RAM17 RAM21 RAM21 ROW17 RAM21 ROW10 RAM10 ROW14 RAM14 ROW10 RAM14 ROW14 RAM22 COM22 ROW16 RAM16 RAM20 RAM20 ROW16 RAM20 ROW9 RAM9 ROW13 RAM13 ROW9 RAM13 ROW13 RAM21 COM23 ROW15 RAM15 RAM19 RAM19 ROW15 RAM19 ROW8 RAM8 ROW12 RAM12 ROW8 RAM12 ROW12 RAM20 COM24 RAM14 RAM18 RAM18 RAM18 RAM7 RAM11 RAM19 ROW14 ROW14 ROW7 ROW11 RAM11 ROW7 ROW11 COM25 RAM13 RAM17 RAM17 RAM17 ROW6 RAM6 ROW10 RAM10 ROW6 RAM10 ROW10 RAM18 COM26 ROW12 RAM12 RAM16 RAM16 ROW12 RAM16 ROW5 RAM5 ROW9 RAM9 ROW5 RAM9 ROW9 RAM17 COM27 ROW11 RAM11 RAM15 RAM15 ROW11 RAM15 ROW4 RAM4 ROW8 RAM8 ROW4 RAM8 ROW8 RAM16 COM28 RAM14 RAM14 RAM14 RAM3 RAM7 RAM7 RAM15 ROW10 RAM10 ROW10 ROW3 ROW7 ROW3 ROW7 COM29 COM30 RAM13 RAM12 RAM13 RAM12 RAM6 RAM5 RAM6 RAM5 RAM13 ROW2 RAM2 ROW6 ROW6 RAM14 RAM8 RAM12 RAM1 RAM13 ROW8 ROW8 ROW1 ROW5 ROW1 ROW5 COM31 ROW7 RAM7 RAM11 RAM11 ROW7 RAM11 ROW0 RAM0 ROW4 RAM4 ROW0 RAM4 ROW4 RAM12 RAM10 RAM10 COM32 ROW6 RAM6 ROW6 RAM10 ROW3 RAM3 ROW3 RAM11 RAMO RAM9 RAM9 RAM8 COM33 RAM ROW5 RAM2 ROW RAM10 RAM8 COM34 ROW4 RAM4 RAM8 ROW4 ROW1 RAM1 ROW1 RAM9 COM35 COM36 RAM7 RAM6 RAM7 RAM6 RAM7 RAM6 ROW3 RAM3 ROW3 ROW0 RAM0 ROW0 RAM8 ROW2 RAM2 ROW2 COM37 COM38 ROW1 RAM1 RAM0 RAM5 ROW4 RAM5 RAM4 ROW1 ROW0 RAM5 RAM4 (b) (e) (a) (c) (d) (f) (q)

Set MUX ration (A8h) COM normal / remap (C0h / C8h) Display offset (D3h) Display start line (40h - 66h)



examples

Solomon Systech Oct 2008 P 40/55 Rev 1.2 SSD1307

9.1.16 Set Display Clock Divide Ratio/ Oscillator Frequency (D5h)

This command consists of two functions:

- Display Clock Divide Ratio (D) (A[3:0])
 Set the divide ratio to generate DCLK (Display Clock) from CLK. The divide ratio is from 1 to 16, with reset value = 0001b. Please refer to section 7.3 for the details relationship of DCLK and CLK.
- Oscillator Frequency (A[7:4])
 Program the oscillator frequency Fosc that is the source of CLK if CLS pin is pulled high. The 4-bit value results in 16 different frequency settings available as shown below. The default setting is 1100b.

9.1.17 Set Pre-charge Period (D9h)

This command is used to set the duration of the pre-charge period. The interval is counted in number of DCLK, where RESET equals to 2 DCLKs.

9.1.18 Set COM Pins Hardware Configuration (DAh)

This command sets the COM signals pin configuration to match the OLED panel hardware layout. Table 8-2 shows the COM pin configuration under different conditions (for MUX ratio = 39).

9.1.19 Set V_{COMH} Deselect Level (DBh)

This command adjusts the VCOMH regulator output.

9.1.20 NOP (E3h)

No Operation Command

9.1.21 Status register Read

This command is issued by setting D/C# ON LOW during a data read (See Figure 12-1 to Figure 12-2 for parallel interface waveform). It allows the MCU to monitor the internal status of the chip. No status read is provided for serial mode.

SSD1307 | Rev 1.2 | P 41/55 | Oct 2008 | **Solomon Systech**

9.2 Graphic Acceleration Command

9.2.1 Horizontal Scroll Setup (26h/27h)

This command consists of consecutive bytes to set up the horizontal scroll parameters and determines the scrolling start page, end page and scrolling speed.

Before issuing this command the horizontal scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted.

The SSD1307 horizontal scroll is designed for 128 columns scrolling. The following two figures (Figure 9-8, Figure 9-9, and Figure 9-10) show the examples of using the horizontal scroll:

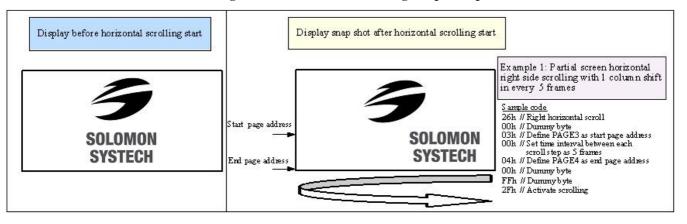
Figure 9-8: Horizontal scroll example: Scroll RIGHT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	:	 	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127
After one scroll step	SEG127	0SEG0	SEG1	SEG2	SEG3	SEG4		 	SEG121	SEG122	SEG123	SEG124	SEG125	SEG126

Figure 9-9: Horizontal scroll example: Scroll LEFT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	:	 :	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127
After one scroll step	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	:	 :	SEG123	SEG124	SEG125	SEG126	SEG127	SEG0

Figure 9-10: Horizontal scrolling setup example



Solomon Systech Oct 2008 | P 42/55 | Rev 1.2 | SSD1307

9.2.2 Continuous Vertical and Horizontal Scroll Setup (29h/2Ah)

This command consists of 6 consecutive bytes to set up the continuous vertical scroll parameters and determines the scrolling start page, end page, scrolling speed and vertical scrolling offset.

The bytes B[2:0], C[2:0] and D[2:0] of command 29h/2Ah are for the setting of the continuous horizontal scrolling. The byte E[5:0] is for the setting of the continuous vertical scrolling offset. All these bytes together are for the setting of continuous diagonal (horizontal + vertical) scrolling. If the vertical scrolling offset byte E[5:0] is set to zero, then only horizontal scrolling is performed (like command 26/27h).

Before issuing this command the scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted. The following figure (Figure 9-11) show the example of using the continuous vertical and horizontal scroll:

Example 1 : Full screen diagonal Display before scrolling start Display snap shot after scrolling start scrolling (horizontal right side scrolling with 1 column shift plus Start page address / vertical scrolling with 1 row up) in No. of rows in top fixed every 6 frames. azea =0 (POR) Sample code 29h // Vertical and right horizontal scroll No. of rows in scroll 00h // Dummybyte 00h // Define PAGE0 as start page address area =39 (POR) 00h // Set time interval between each scroll step as 6 frames 04h // Define PAGE4 as end page address End page address 01h #Set vertical scrolling offset as 1 row 2Fh // Activate scrolling

Figure 9-11: Continuous Vertical and Horizontal scrolling setup example

9.2.3 Deactivate Scroll (2Eh)

This command stops the motion of scrolling. After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.

9.2.4 Activate Scroll (2Fh)

This command starts the motion of scrolling and should only be issued after the scroll setup parameters have been defined by the scrolling setup commands: 26h / 27h / 29h / 2Ah. The setting in the latest scrolling setup command overwrites the setting in the previous scrolling setup command.

The following actions are prohibited after the scrolling is activated

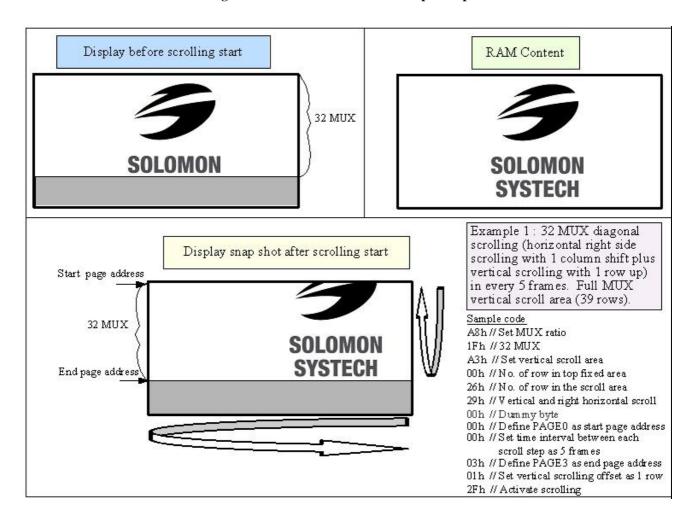
- 1. RAM access (Data write or read)
- 2. Changing the horizontal scroll setup parameters

9.2.5 Set Vertical Scroll Area (A3h)

This command consists of 3 consecutive bytes to set up the vertical scroll area. For the continuous vertical scroll function (command 29h / 2Ah), the number of rows in the vertical scroll area can be set smaller than or equating to the MUX ratio. Figure 9-12 shows some vertical scrolling example with different settings in vertical scroll area.

SSD1307 | Rev 1.2 | P 43/55 | Oct 2008 | **Solomon Systech**

Figure 9-12: Vertical scroll area setup examples



Solomon Systech Oct 2008 | P 44/55 | Rev 1.2 | SSD1307

10 MAXIMUM RATINGS

Table 10-1 : Maximum Ratings (Voltage Referenced to $V_{SS}\!)$

Symbol	Parameter	Value	Unit
$V_{ m DD}$	Supply Voltage	-0.3 to +4	V
V_{CC}	Supply voltage	0 to 16	V
V_{SEG}	SEG output voltage	0 to V _{CC}	V
V_{COM}	COM output voltage	0 to 0.9*V _{CC}	V
V _{in}	Input voltage	V_{SS} -0.3 to V_{DD} +0.3	V
T_{A}	Operating Temperature	-40 to +85	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

SSD1307 Rev 1.2 P 45/55 Oct 2008 **Solomon Systech**

11 DC CHARACTERISTICS

Condition (Unless otherwise specified):

Voltage referenced to V_{SS} , $V_{DD} = 1.65 \text{ V}$ to 3.3 V, $T_A = 25 ^{\circ}\text{C}$

Table 11-1: DC Characteristics

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit	
V _{CC}	Operating Voltage	-	7	-	15	V	
V_{DD}	Logic Supply Voltage	-	1.65	-	3.3	V	
V_{OH}	High Logic Output Level	$I_{OUT} = 100uA, 3.3MHz$	$0.9 \times V_{DD}$	-	-	V	
V_{OL}	Low Logic Output Level	$I_{OUT} = 100uA, 3.3MHz$	-	-	$0.1 \times V_{DD}$	V	
V_{IH}	High Logic Input Level	-	$0.8 \times V_{DD}$	-	-	V	
$V_{\rm IL}$	Low Logic Input Level	-	-	-	$0.2 \times V_{DD}$	V	
$I_{\text{DD,SLEEP}}$	Sleep mode Current	$V_{DD} = 1.65 V \sim 3.3 V$, $V_{CC} = 7 V \sim 15 V$ Display OFF, No panel attached	-	-	10	uA	
I _{CC,SLEEP}	Sleep mode Current	$V_{DD} = 1.65V \sim 3.3V$, $V_{CC} = 7V \sim 15V$ Display OFF, No panel attached	-	-	10	uA	
I_{CC}	V_{CC} Supply Current $V_{DD} = 2.8V$, $V_{CC} = 12$, $I_{REF} = 10uA$, No loading, Display ON, All ON	Control FEL	-	455	590	uA	
I_{DD}	V_{DD} Supply Current V_{DD} =2.8V, V_{CC} = 12, I_{REF} = 10uA, No loading, Display ON, All ON,	Contrast = FFh	-	23	30	uA	
	Commant Outroot Commant	Contrast=FFh	285	316	345		
	Segment Output Current, $V_{DD} = 2.8V$,	Contrast=AFh	-	217	-		
I_{SEG}	$V_{CC}=12V$	Contrast=7Fh	-	158	-	uA	
	I _{REF} =10uA,	Contrast=3Fh	-	78	-		
	Display ON.	Contrast=0Fh	-	19	-		
Dev	Segment output current uniformity	$\begin{aligned} & Dev = (I_{SEG} - I_{MID})/I_{MID} \\ & I_{MID} = (I_{MAX} + I_{MIN})/2 \\ & I_{SEG}[0:127] = Segment \ current \\ & at \ contrast \ setting \ range = 3Fh \ to \ FFh \end{aligned}$	-3	-	3	%	
Adj. Dev	Adjacent pin output current uniformity (contrast setting range = 3Fh to FFh)	Adj Dev = (I[n]-I[n+1]) / (I[n]+I[n+1])	-2	-	2	%	

 Solomon Systech
 Oct 2008
 P 46/55
 Rev 1.2
 SSD1307

12 AC CHARACTERISTICS

Conditions:

Voltage referenced to V_{SS} V_{DD} =1.65 to3.3V T_A = 25°C

Table 12-1: AC Characteristics

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
Fosc (1)	Oscillation Frequency of Display Timing Generator	$V_{DD} = 2.8V$	378	420	462	kHz
FFRM	Frame Frequency for 39 MUX Mode	128x39 Graphic Display Mode, Display ON, Internal Oscillator Enabled	-	F _{OSC} x 1/(DxKx39)	-	Hz
RES#	Reset low pulse width		3	-	-	us

Note

SSD1307 Rev 1.2 P 47/55 Oct 2008 **Solomon Systech**

 $^{^{(1)}}$ Fosc stands for the frequency value of the internal oscillator and the value is measured when command D5h A[7:4] is in default value.

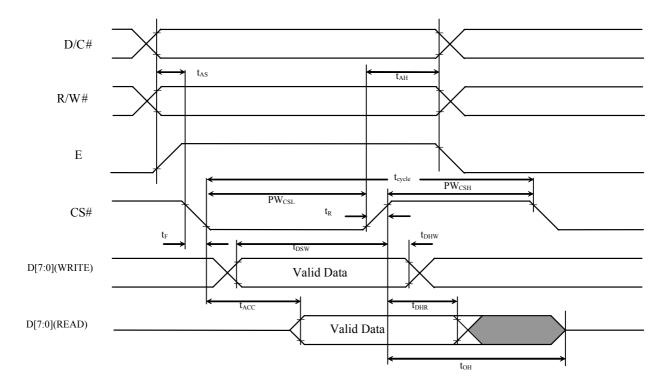
 ⁽²⁾ D: divide ratio (default value = 2)
 K: number of display clocks per row period (default value = 54)
 Please refer to Table 8-1 (Set Display Clock Divide Ratio/Oscillator Frequency, D5h) for detailed description

Table 12-2: 6800-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65V \text{ to } 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter Parameter	Min	Тур	Max	Unit
$t_{\rm cycle}$	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
$t_{ m AH}$	Address Hold Time	0	-	-	ns
$t_{ m DSW}$	Write Data Setup Time	40	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	7	-	-	ns
$t_{ m DHR}$	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
PW _{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	40	ns
$t_{\rm F}$	Fall Time	-	-	40	ns

Figure 12-1 : 6800-series MCU parallel interface characteristics



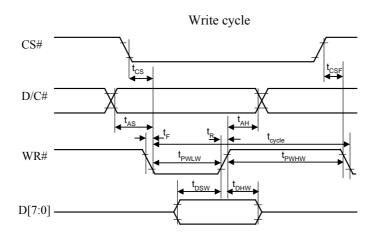
 Solomon Systech
 Oct 2008
 P 48/55
 Rev 1.2
 SSD1307

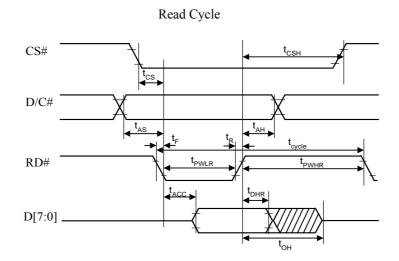
Table 12-3: 8080-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65V \sim 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter	Min	Тур	Max	Unit
$t_{\rm cycle}$	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	10	-	1	ns
t_{AH}	Address Hold Time	0	=.	-	ns
$t_{ m DSW}$	Write Data Setup Time	40	-	1	ns
$t_{ m DHW}$	Write Data Hold Time	7	-	1	ns
t_{DHR}	Read Data Hold Time	20	-	1	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	•	-	140	ns
t_{PWLR}	Read Low Time	120	-	1	ns
t_{PWLW}	Write Low Time	60	-	1	ns
t_{PWHR}	Read High Time	60	-	1	ns
t_{PWHW}	Write High Time	60	-	1	ns
t_R	Rise Time	•	-	40	ns
t_{F}	Fall Time	-	_	40	ns
t_{CS}	Chip select setup time	0	_	-	ns
t_{CSH}	Chip select hold time to read signal	0	-	-	ns
t_{CSF}	Chip select hold time	20	-	-	ns

Figure 12-2: 8080-series parallel interface characteristics





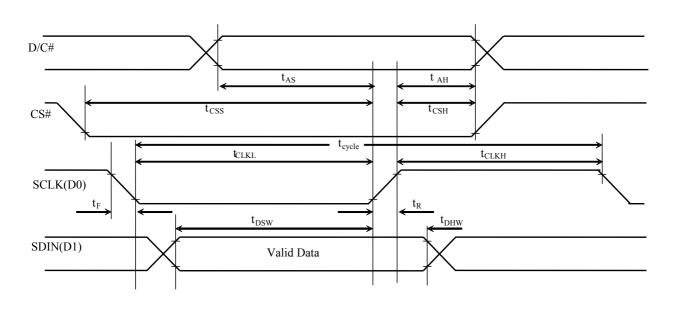
SSD1307 Rev 1.2 P 49/55 Oct 2008 **Solomon Systech**

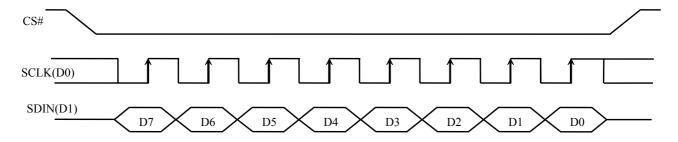
Table 12-4: Serial Interface Timing Characteristics (4-wire SPI)

 $(V_{DD} - V_{SS} = 1.65V \sim 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	100	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
$t_{ m DSW}$	Write Data Setup Time	15	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	15	-	-	ns
$t_{\rm CLKL}$	Clock Low Time	20	-	-	ns
t_{CLKH}	Clock High Time	20	-	-	ns
t_{R}	Rise Time	-	-	40	ns
t_{F}	Fall Time	-	-	40	ns

Figure 12-3: Serial interface characteristics (4-wire SPI)





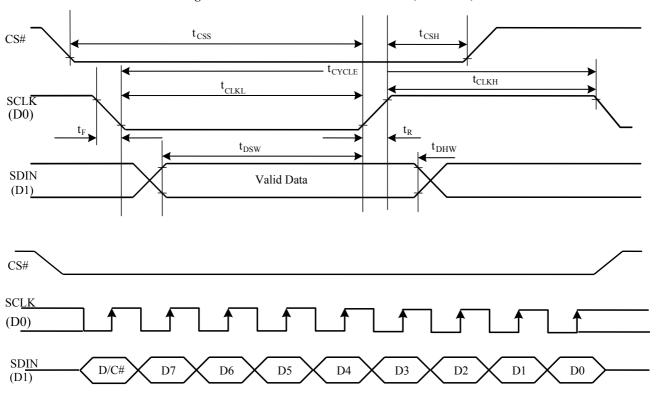
 Solomon Systech
 Oct 2008
 P 50/55
 Rev 1.2
 SSD1307

Table 12-5: Serial Interface Timing Characteristics (3-wire SPI)

 $(V_{DD} - V_{SS} = 1.65V \sim 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter	Min	Тур	Max	Unit
$t_{\rm cycle}$	Clock Cycle Time	100	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	20	-	-	ns
t_{CLKH}	Clock High Time	20	-	-	ns
t_R	Rise Time	-	-	40	ns
$t_{\rm F}$	Fall Time	-	-	40	ns

Figure 12-4 : Serial interface characteristics (3-wire SPI)



SSD1307 Rev 1.2 P 51/55 Oct 2008 **Solomon Systech**

Conditions:

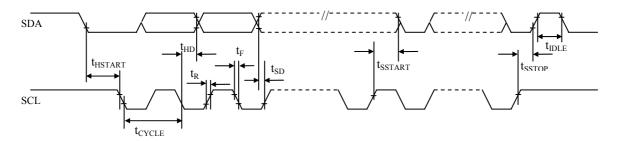
$$V_{DD} - V_{SS} = 1.65 V \sim 3.3 V$$

 $T_A = 25^{\circ}C$

Table 12-6: I²C Interface Timing Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	2.5	-	-	us
t _{HSTART}	Start condition Hold Time	0.6	-	-	us
$t_{ m HD}$	Data Hold Time (for "SDA _{OUT} " pin)	0	-	-	ns
	Data Hold Time (for "SDA _{IN} " pin)	300	-	-	ns
t_{SD}	Data Setup Time	100	-	-	ns
t_{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t_{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t_R	Rise Time for data and clock pin	-	-	300	ns
$t_{\rm F}$	Fall Time for data and clock pin	-	-	300	ns
$t_{ m IDLE}$	Idle Time before a new transmission can start	1.3	-	-	us

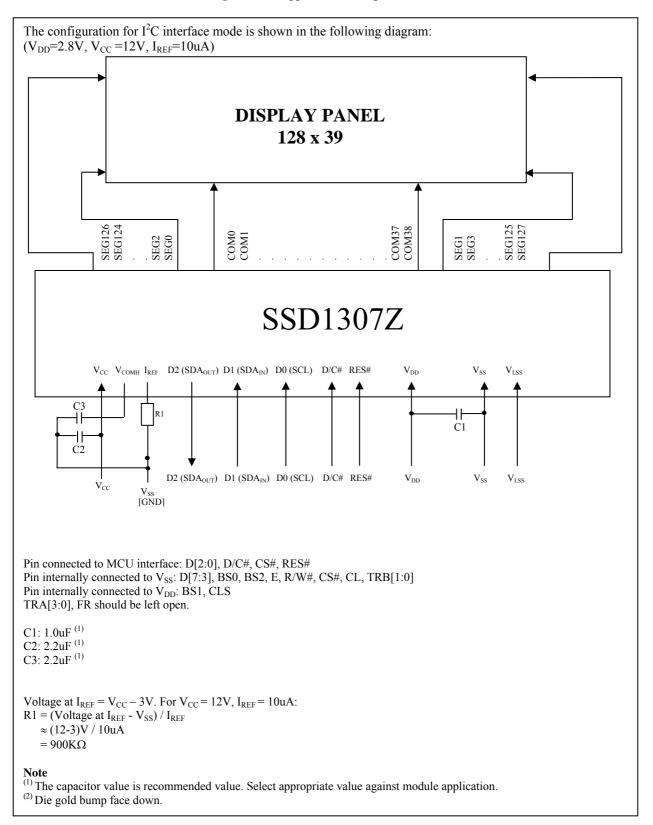
Figure 12-5: I²C interface Timing characteristics



 Solomon Systech
 Oct 2008
 P 52/55
 Rev 1.2
 SSD1307

13 Application Example

Figure 13-1: Application Example of SSD1307Z

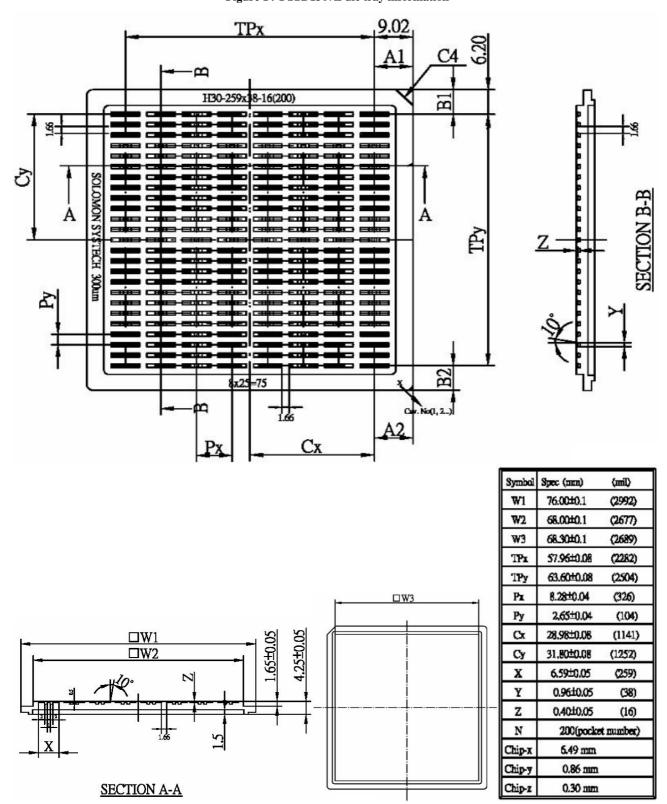


SSD1307 | Rev 1.2 | P 53/55 | Oct 2008 | **Solomon Systech**

14 PACKAGE INFORMATION

14.1 SSD1307Z Die Tray Information

Figure 14-1 SSD1307Z die tray information



 Solomon Systech
 Oct 2008 | P 54/55 | Rev 1.2 |
 SSD1307

Solomon Systech reserves the right to make changes without notice to any products herein. Solomon Systech makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Solomon Systech assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any, and all, liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typical" must be validated for each customer application by the customer's technical experts. Solomon Systech does not convey any license under its patent rights nor the rights of others. Solomon Systech products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Solomon Systech product could create a situation where personal injury or death may occur. Should Buyer purchase or use Solomon Systech products for any such unintended or unauthorized application, Buyer shall indemnify and hold Solomon Systech and its offices, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Solomon Systech was negligent regarding the design or manufacture of the part.

http://www.solomon-systech.com